

Detectors R&D at CIAE Beijing

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Outline

- **Developments of MPGD**
- **R&D of GEM at CIAE**
- **R&D of MicroMegas at CIAE**
- **Developments of EMCal Detector for sPHENIX**
- **ALICE Upgrade**
- **Summary and Perspective**



Development of MPGD

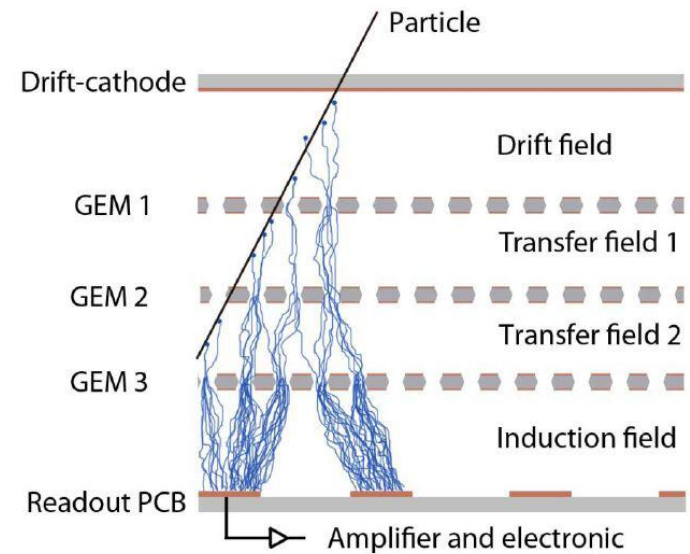
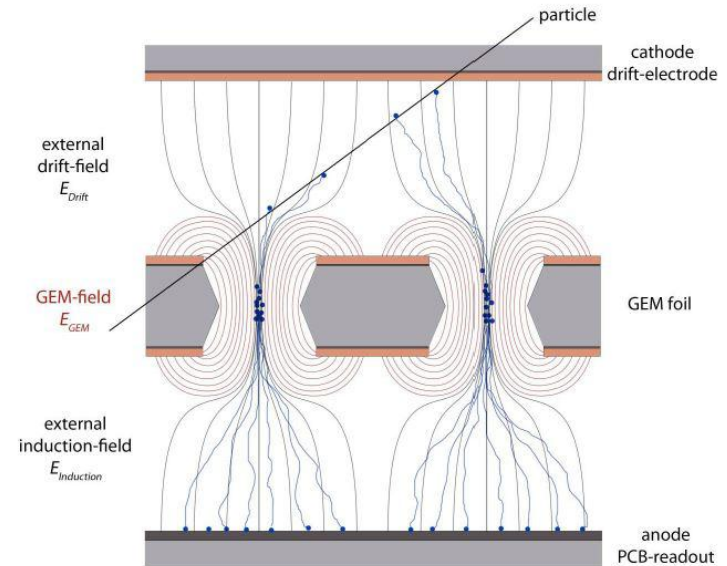


R&D of GEM at CIAE



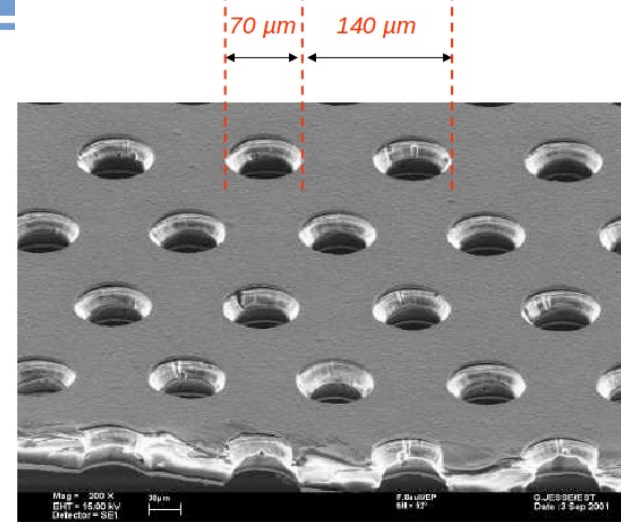
Structure of GEM

- **GEM detector:**
 - Cathode, Drift field, GEM foil, Induction field and Readout board.
 - **GEM foil: the most important part of GEM detector . Normally 3 GEM foils in one GEM detector.**

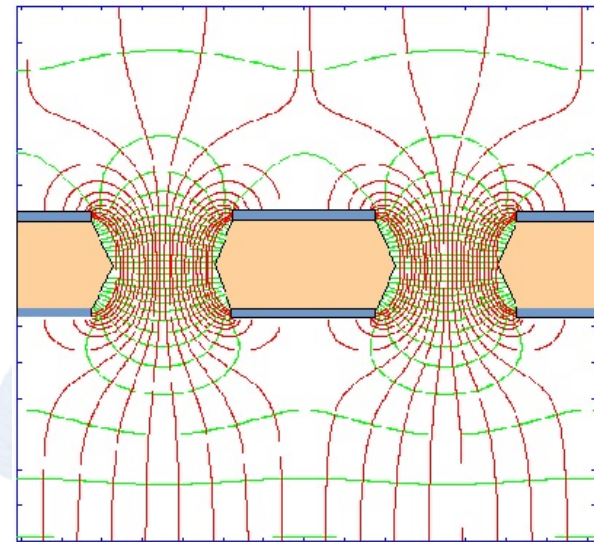


GEM Foil

1. Typical GEM Foil has 3 layers, two $5\mu\text{m}$ thick copper foils and one $50\mu\text{m}$ thick kapton foil in the middle.
2. Diameter of the hole is $70\mu\text{m}$, and the distance between them is $140\mu\text{m}$.
3. Apply electric voltages on the two copper layers.
4. Electric Field is very strong in the hole area, and weak outside the hole area.



GEM Foil

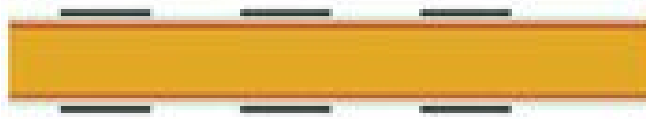


GEM Field



The Procedure of GEM Foil

Double mask photolithography



50 μm kapton foil 5 μm
copper clad on both sides

Photoresist coating,
masking, exposure

Photoresist development,
copper etching

Kapton etching

Metal etching

Second masking,
exposure

Development, etching,
final cleaning

Single mask photolithography



GEM License and Training

CIAE is the first chinese institution which signed officially the LICENSE AGREEMENT FOR MANUFACTURING AND COMMERCIALISATION OF GEM FOILS AND GEM-BASED PRODUCTS with CERN.

I took a training for GEM foil at CERN.



北京市275信箱

Photolithography Room Construction At CIAE



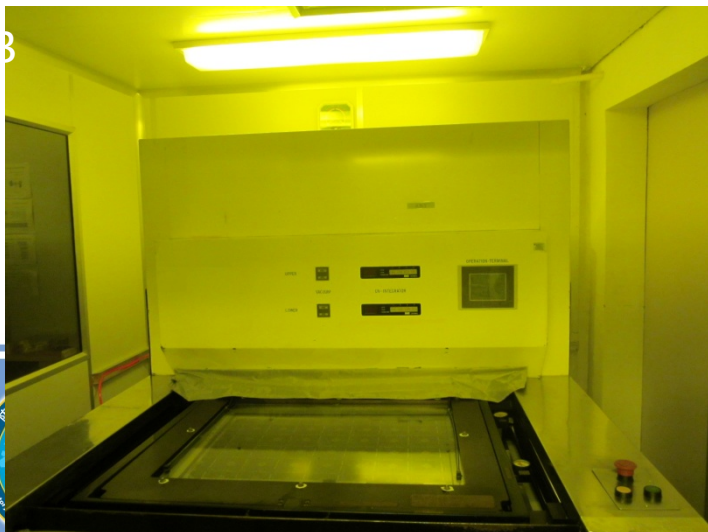
The Equipments for Lamination and Exposure of Dry Film Photoresist



Lamination and exposure of dry film photoresist are the most important and difficult steps for GEM foil production.

We have established a yellow light zone, Hot Roll Lamination (HRL) machine and Exposure system.

We invited a senior engineer from a famous electronic factory to CIAE and taught the PCB technology.



Exposure of Dry Film Photoresist

We use negative photoresist for GEM image transfer, unexposed areas are relatively unchanged and easily washed out during the development.

To obtain an identical copy of the photo-mask to the photoresist, vertical sidewalls in the resist are important.

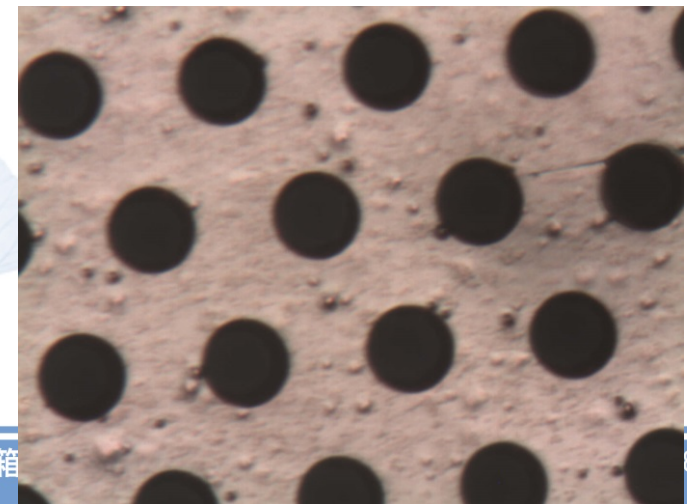
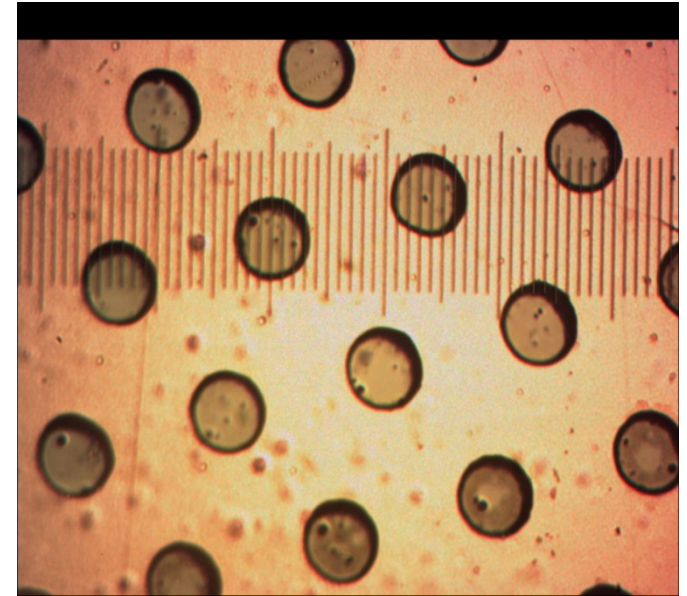


We can observe the image transfer with good accuracy.



Copper Etching and Kapton Etching

- The size of the hole is 70um as expected

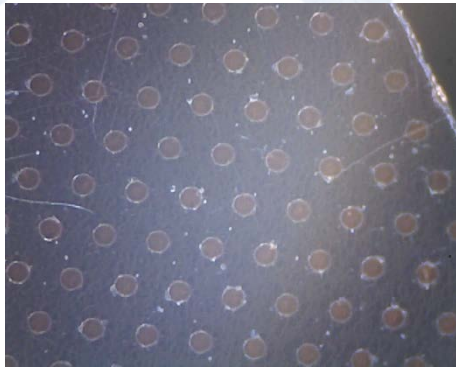


Etching Room Construction



Comparison of Foils Made in Different Conditions

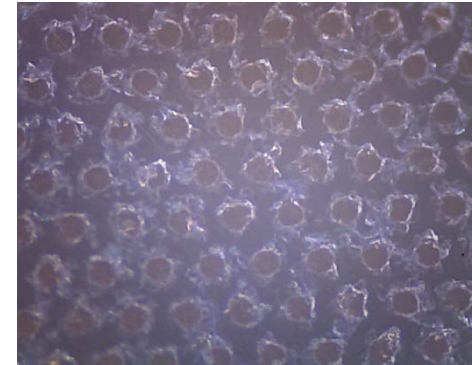
Insufficient development



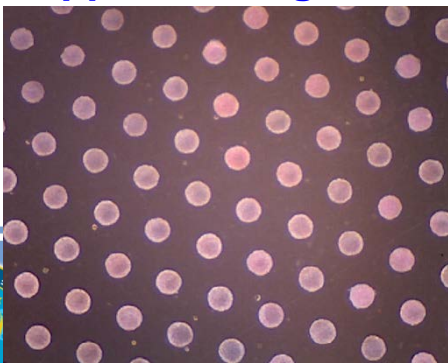
Good development



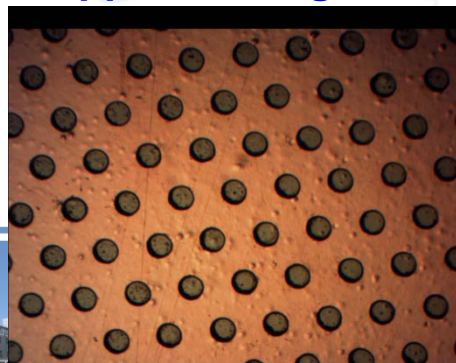
Excessive development



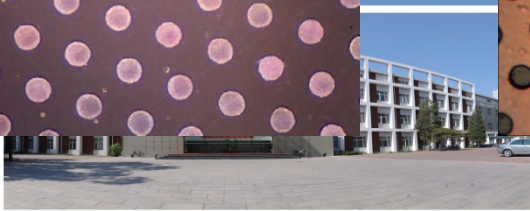
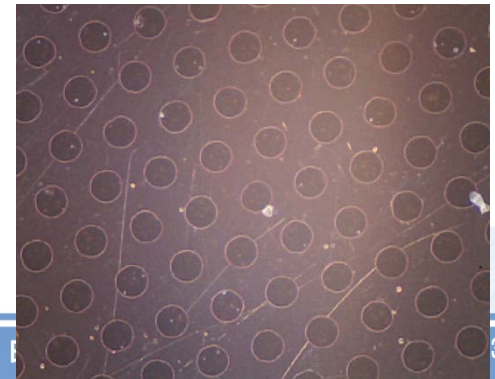
Insufficient copper etching



Good copper etching

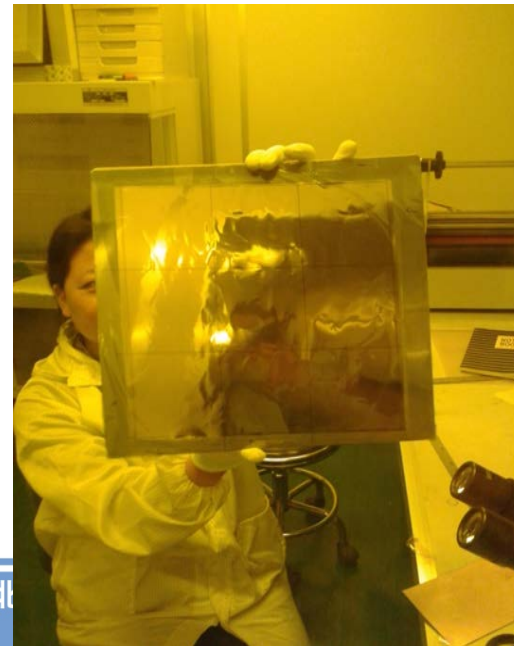
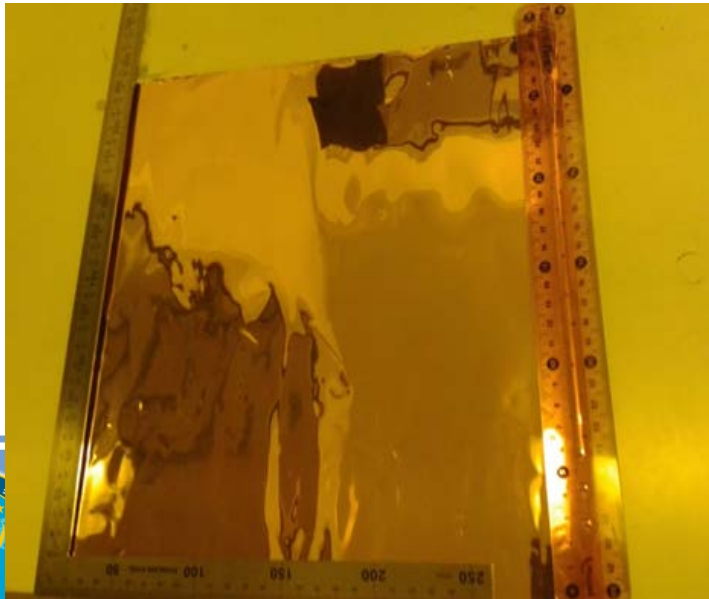


Excessive copper etching

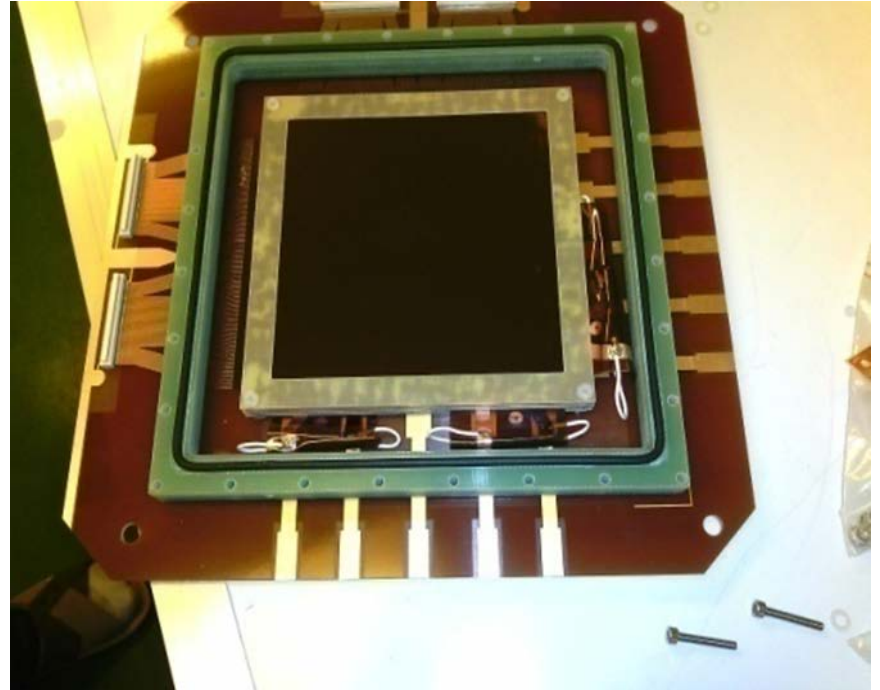
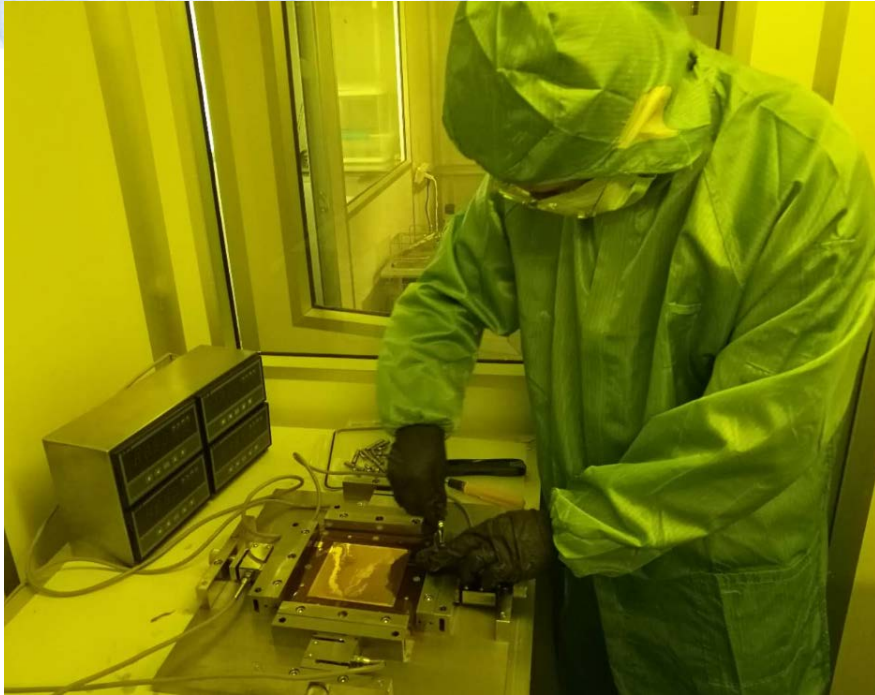


50cm*50cm GEM Foil

- The 50cm*50cm GEM foils were made successfully.
- single-mask method was used.
- We did more than 200 samples before reaching this result.
- Sometimes the alignments of top and bottom masks were not perfect especially for large GEM foil. We have upgraded our alignment system.



GEM Detector Assembly at CIAE



active area 10*10cm



Spatial resolution

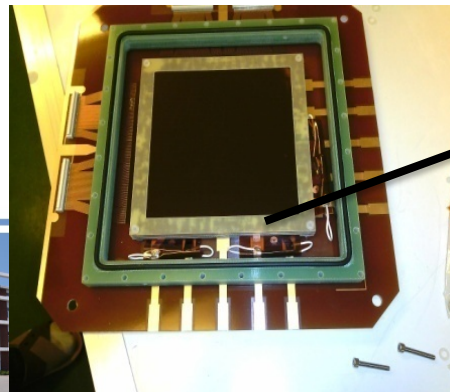
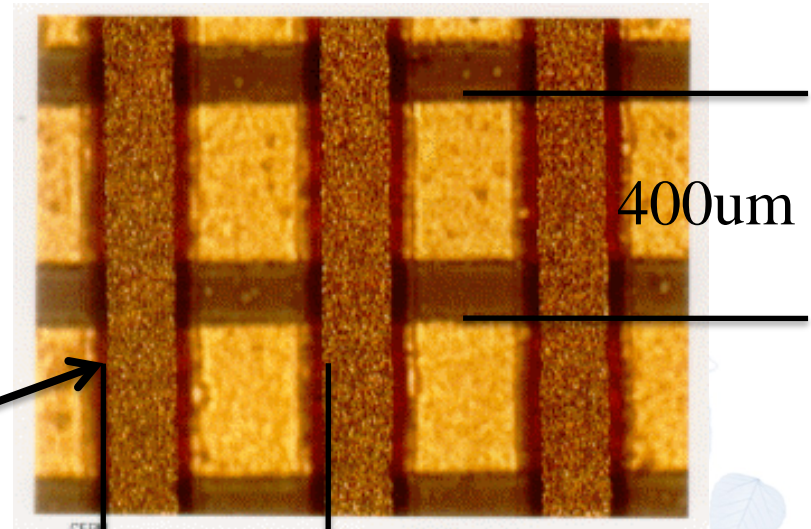
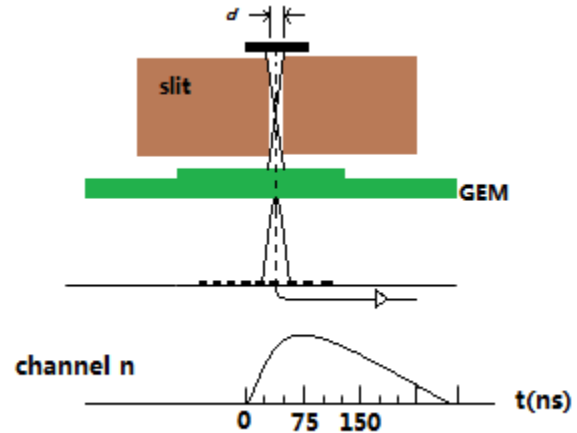
$$\sigma_{\text{tot}}^2 = \sigma_{\text{GEM}}^2 + c_1 \sigma_{\text{geometry}}^2$$

When: $\sigma_{\text{geometry}} \ll \sigma_{\text{GEM}}$

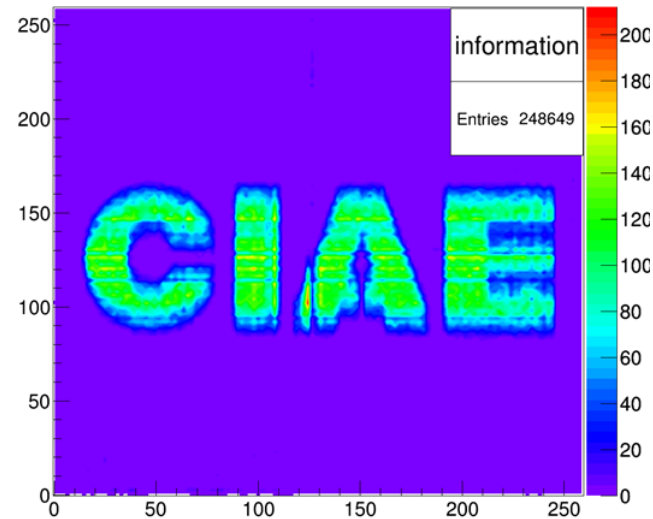
$$\sigma_{\text{tot}}^2 \cong \sigma_{\text{GEM}}^2$$

Spatial resolution $\approx 76\mu\text{m}$

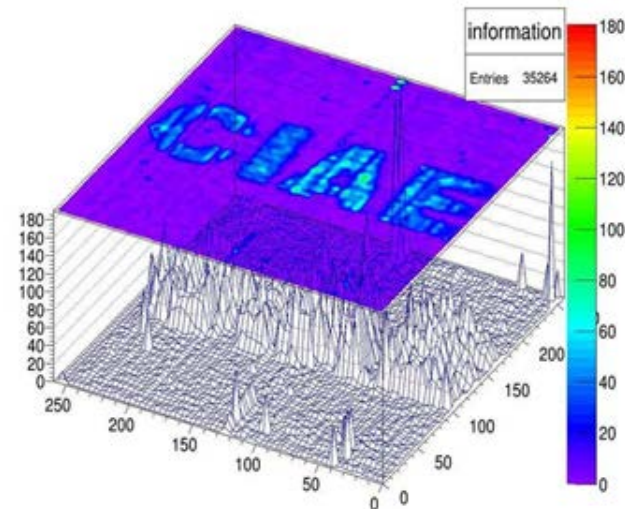
- Slit(μm): 20;
- Ar: CO₂=70% : 30%;
- HV: 3600V;
- The distance between strips: 400 μm .



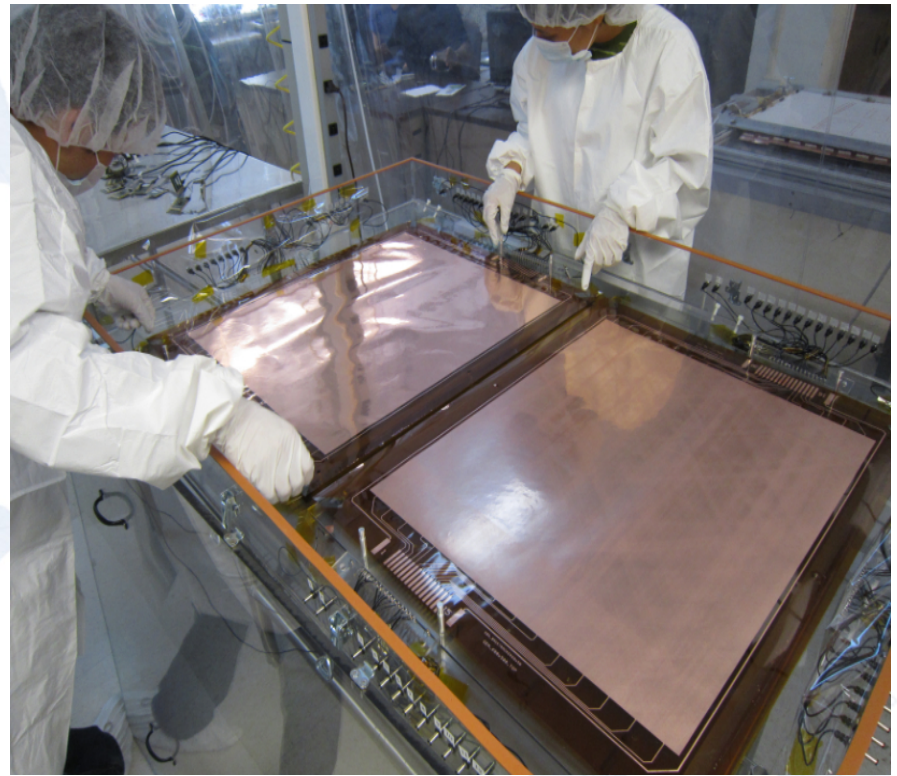
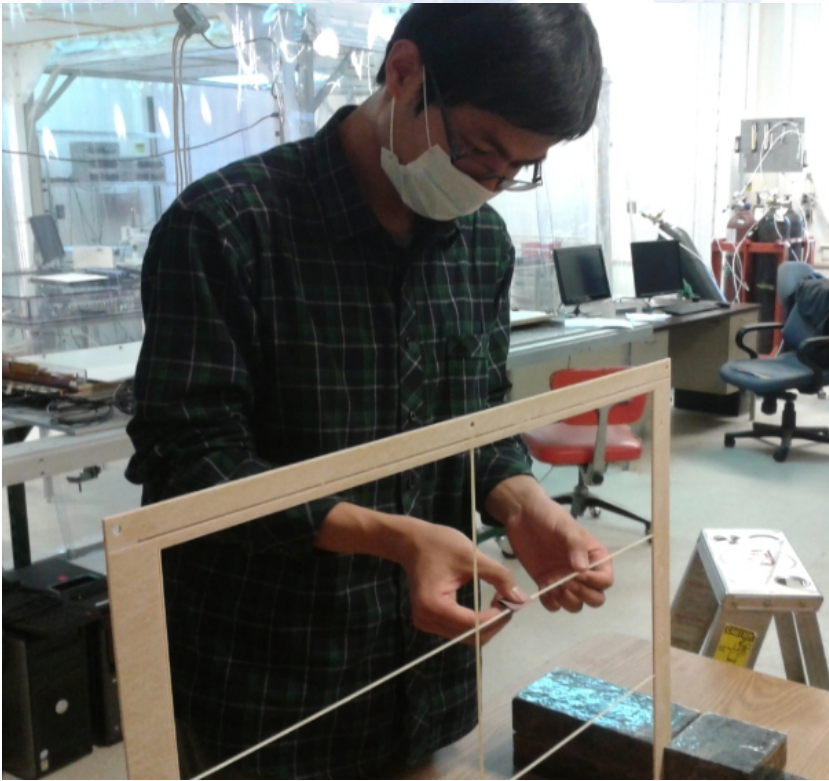
X-ray imaging @ CIAE



- X ray Energy: 8.9keV;
- 256 channels for each dimension(512 channel in total);
- 4 APV FECs were used (2 for each dimension)



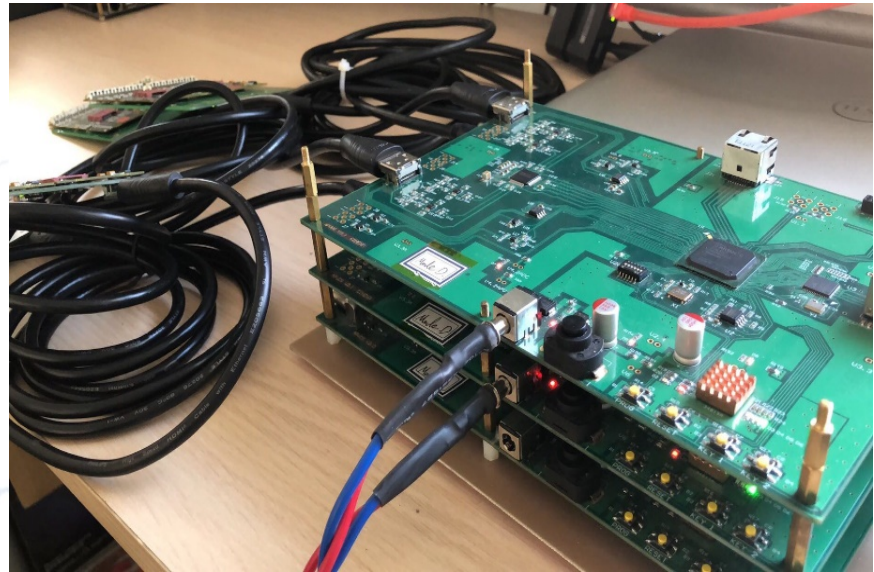
Students working at JLAB and UVA



Electronic and DAQ System for MPGD

The Electronic and DAQ System developed with *APV25* electronics front-end card, *APVDS* electronic digital system and new data acquisition software *GeoAPV*.

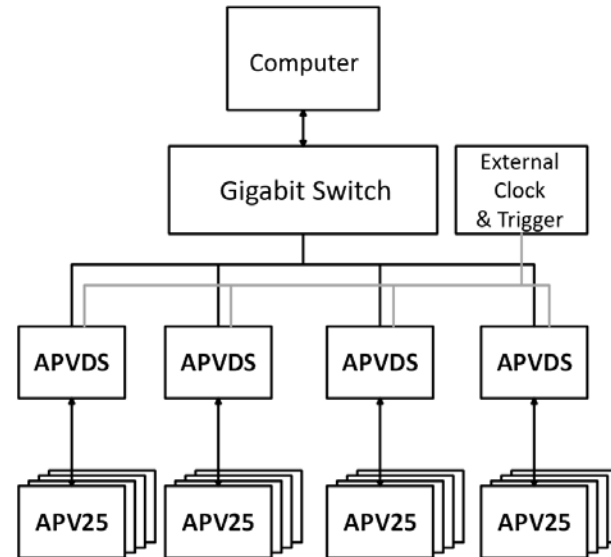
Testing in the configuration of 2,048 channels, internal trigger mode while monitoring the sampling waveform, the transmission rate can stably maintain 715 Mbps



Electronic Hardware Integration

Each APVDS digitalization board is capable of processing 512 channels' input.

The whole system uses multiple APVDS board to expand the capacity of the system.



Every APVDS has an independent IP address and shares a common external clock signal from APVTTS board.



R&D of MicroMegs at CIAE



Micromegas Classifications

– Classic Micromegas

- Mesh on a frame

– Bulk Micromegas

- photolithography process is used to attach the mesh on the PCB.

– Microbulk Micromegas

- Mesh and PCB made on a unique kapton foil, the mesh layer is thinner.

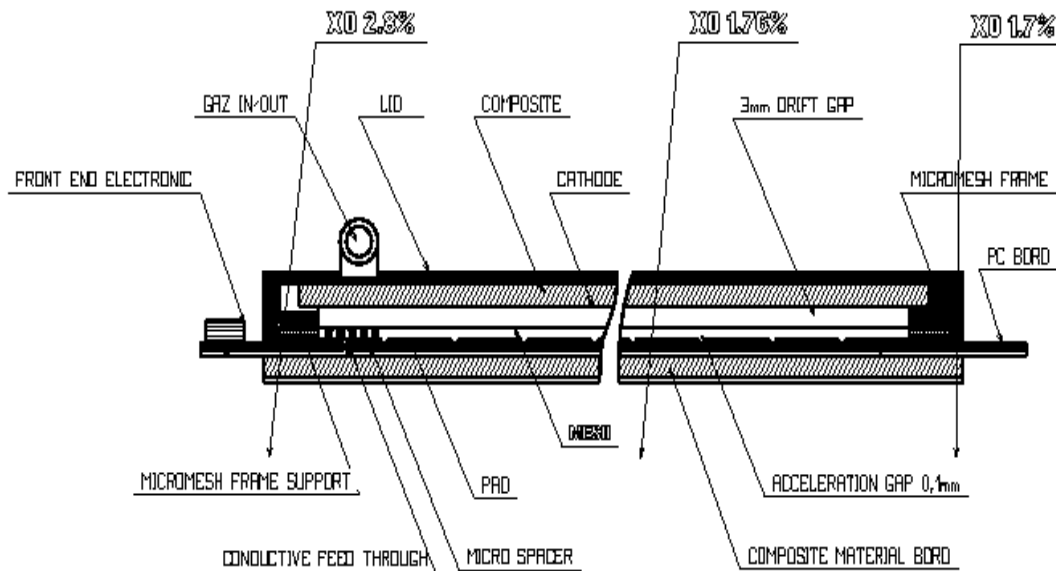


13/06/2024



MICROME GAS detector

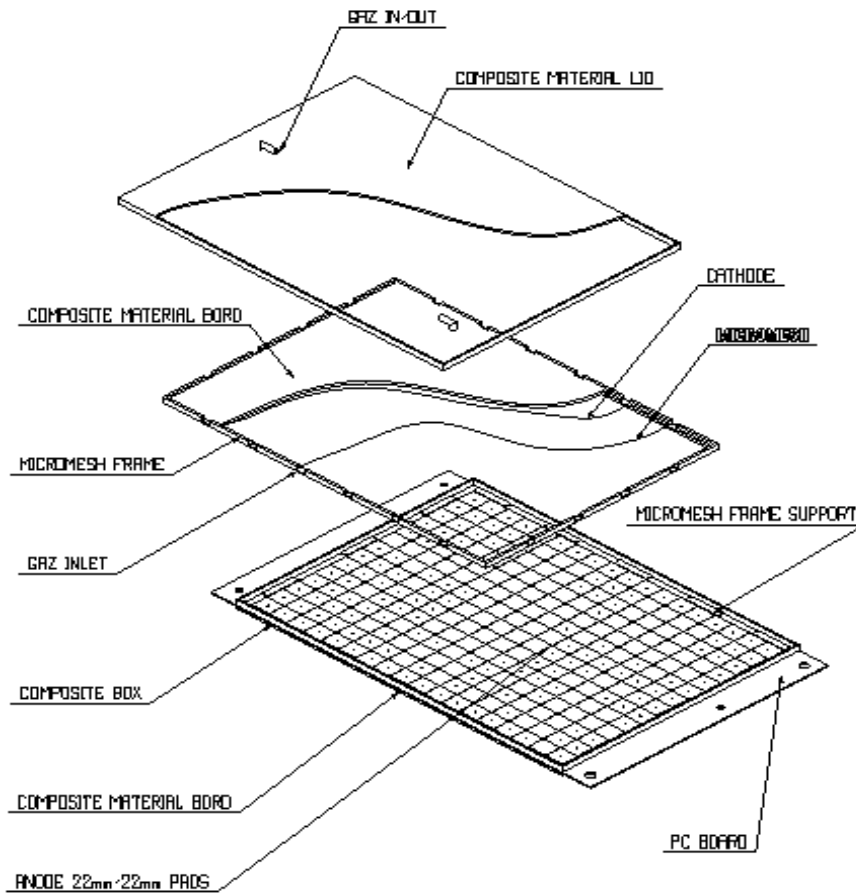
- active area $415 \times 375 \text{mm}^2$
- 3mm drift gap
- $100 \mu\text{m}$ amplification gap
- a high electric field in the amplification region (50kV/cm)
- a low electric field in the drift region (2kV/cm)



Ph.D in SUBATECH,
France



MICROMEGAS detector



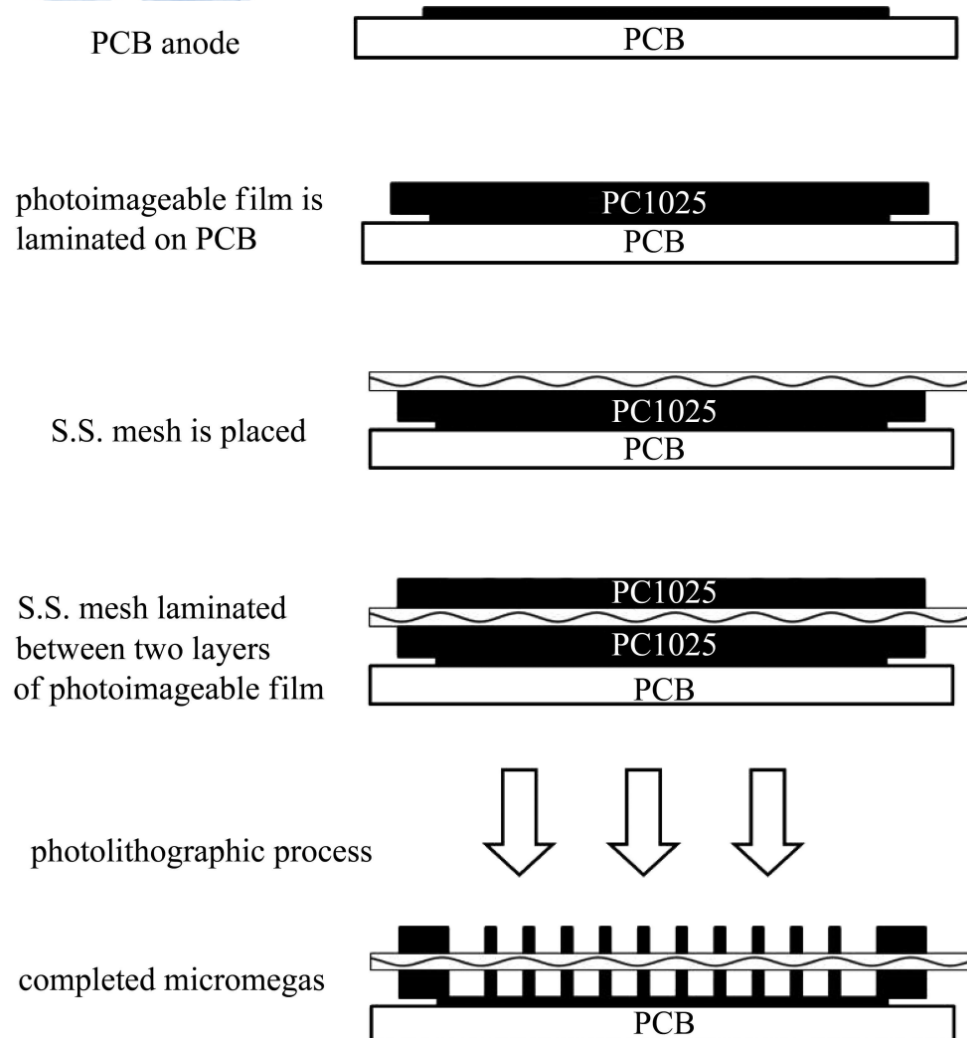
- The anode is made of a 1.0mm thick electronic board(GI180) on one side with $2.2*2.2 \text{ cm}^2$ copper pad on other side with signal collecting strip
- The micromesh is made of pure Nickel
- The cathode consists of $9 \mu\text{m}$ layer of copper, glued on a 3mm thick plate made of composite material

Two different designs to keep micro-spacers

1. The amplification gap is defined by cylindrical micro-spacers of $200\ \mu\text{m}$ high and $250\ \mu\text{m}$ in diameter, glued on to the anode-pads with a pitch of 2 mm in both directions.
2. The micro-spacers are replaced by an insulating grid sandwiched between the micro-mesh and the anode plane



Structure of Bulk MicroMegas

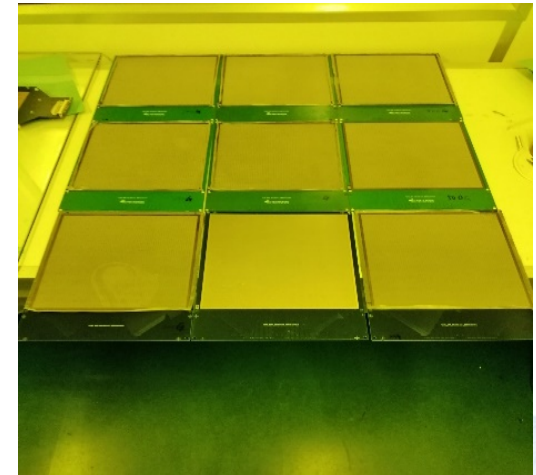


Reference: Study of bulk micromegas detector
Chinese Physics C Vol. 34, No. 10, Oct., 2010

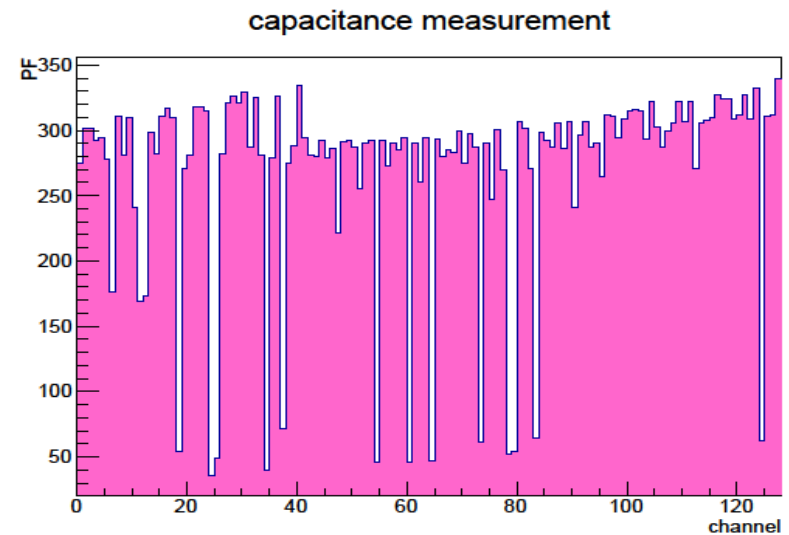


Manufacture of MicroMegas at CIAE

- Completed R&D and mass production of bulk MicroMegas.
- Developed new photoetching MicroMegas, applied for 13 patents, obtained 1 international patent.

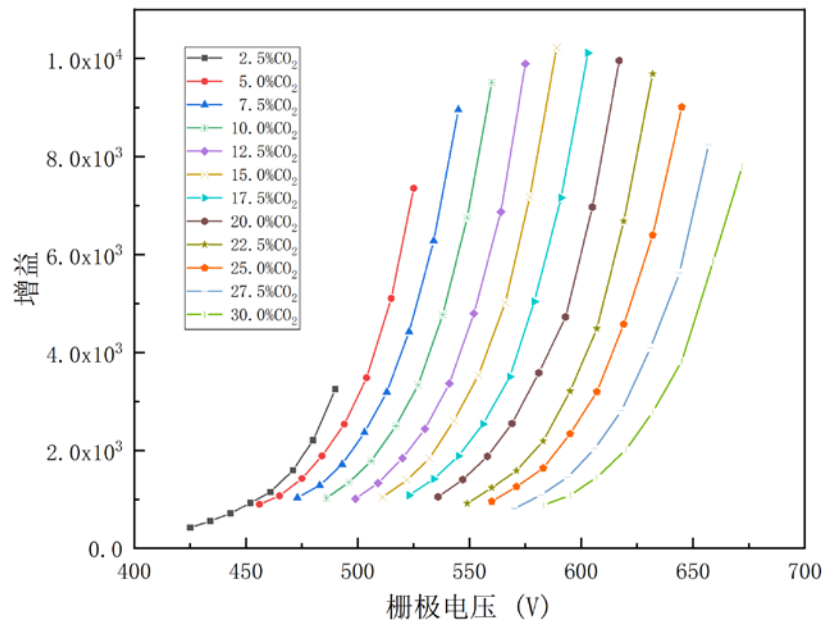


Capacitance and Resistance Automatic Testing System Invented by CIAE



Performance of Micromegas

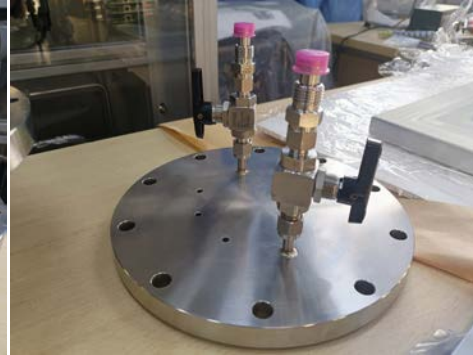
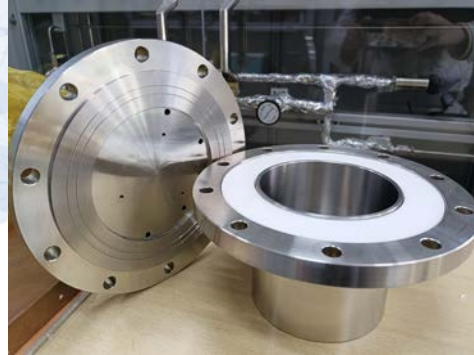
The gain of the detector varies with the grid voltage under different ratios of Ar and CO₂ working gases



The Micromegas developed independently by our team achieves the best energy resolution of 17.5% in Ar and iC₄H₁₀ gases. It has reached the best level of energy resolution of similar multi-channel non-resistive Micromegas in the world.

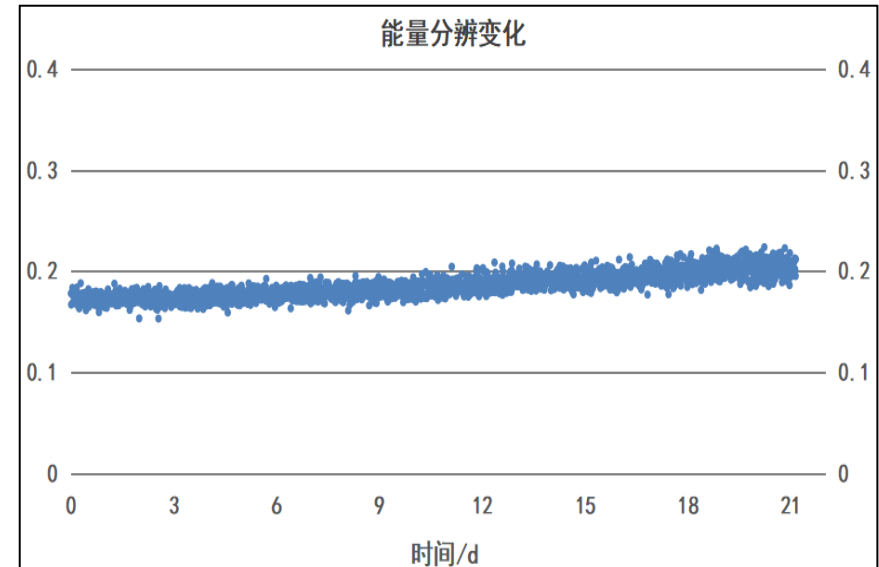
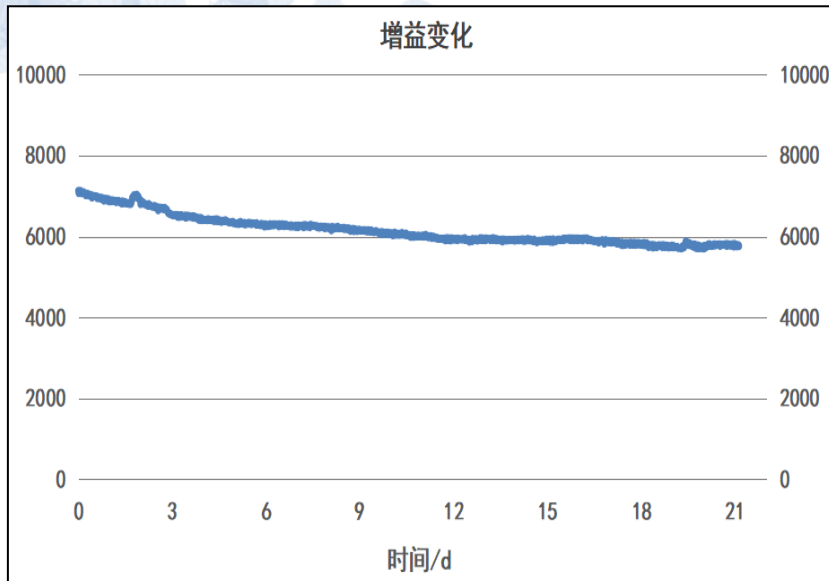


Development of Sealed Chamber MM



Development of Sealed Chamber MM

$V_{\text{Mesh}}: 510\text{V}$ $V_{\text{Drift}} 900\text{V}$

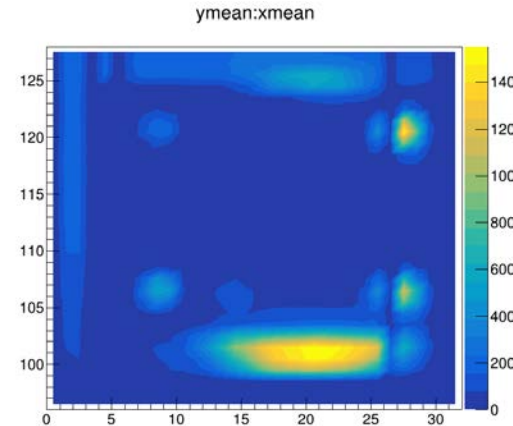
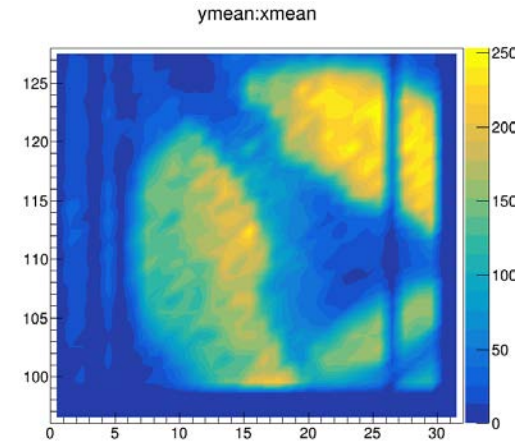


The energy resolution of the sealed micro-pattern gas detector has consistently remained at an excellent level after 21 days of continuous measurement.

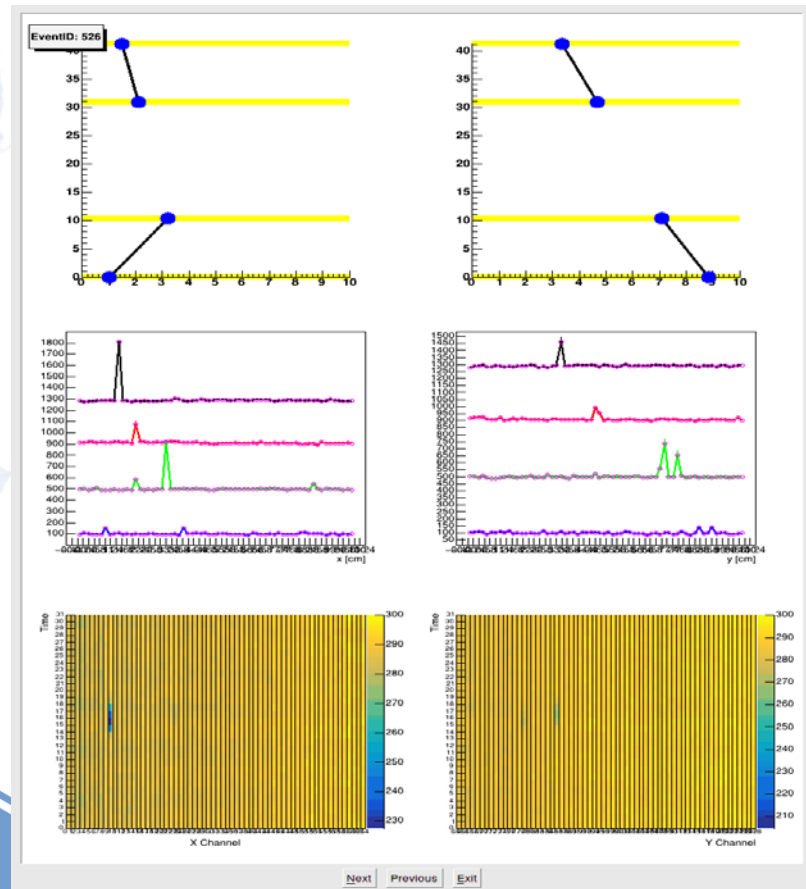


Micromegas X-Ray Imaging

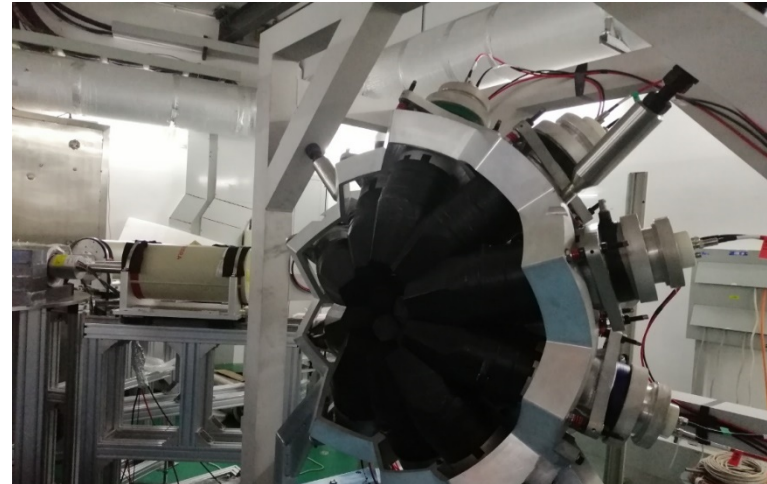
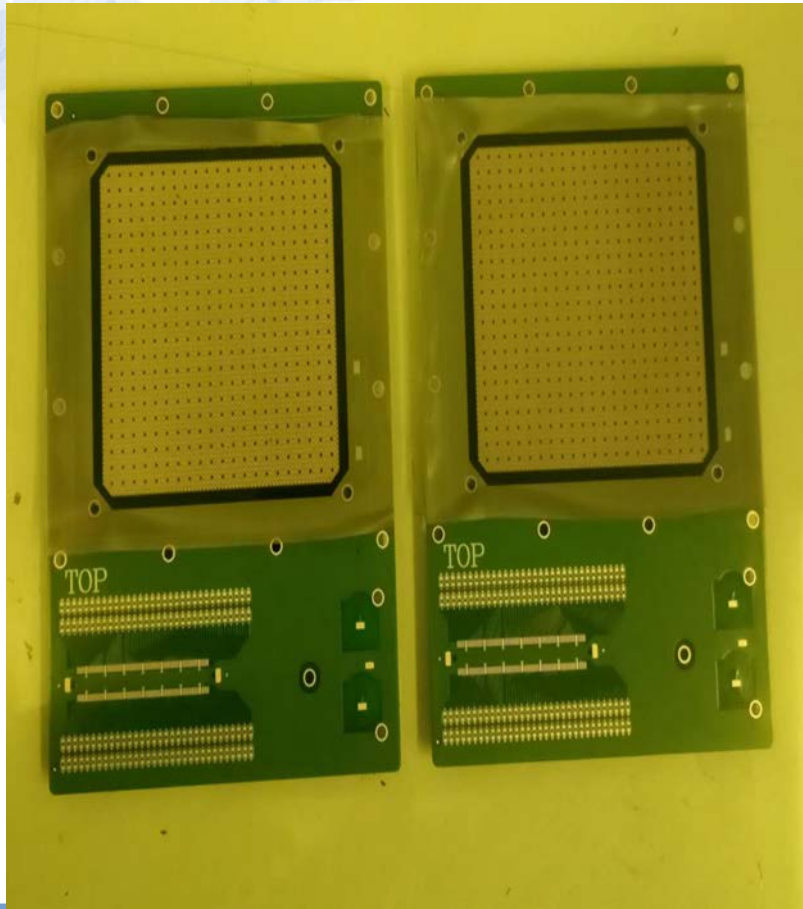
- Argon + 30%CO₂
- Mesh: -550V(max -620V)
- Drift: -2500V
- 50kV X-Ray tube



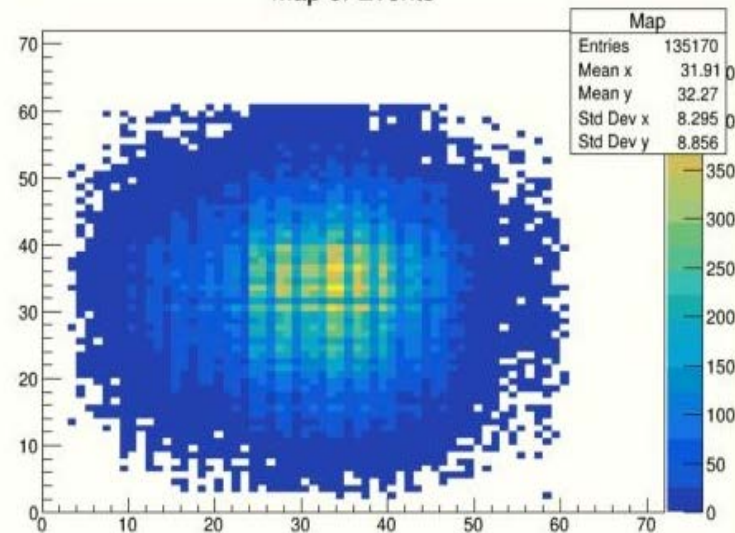
MicroMegas: Radiation Detection



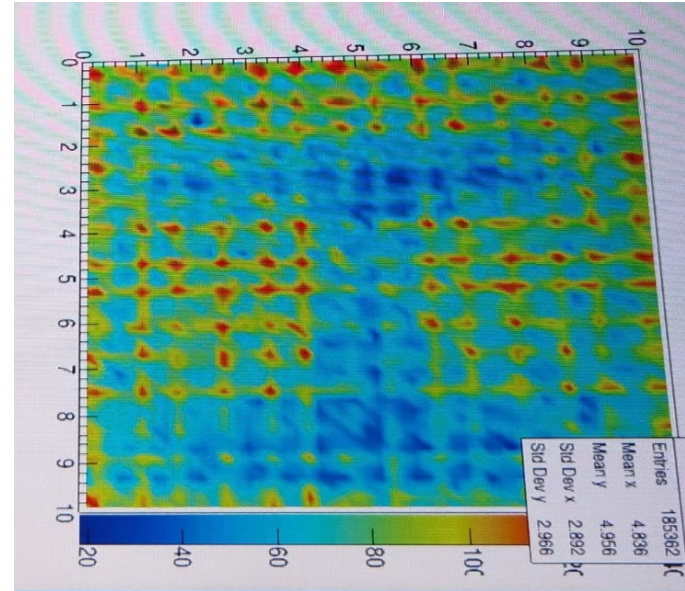
Neutron imaging at China Spallation Neutron Source



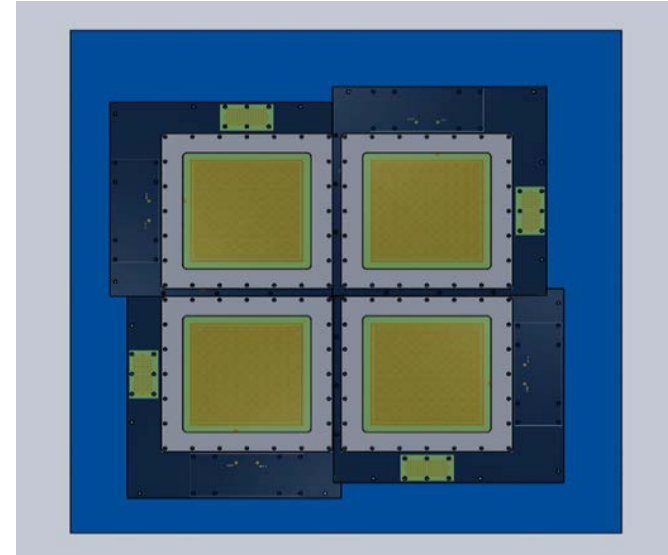
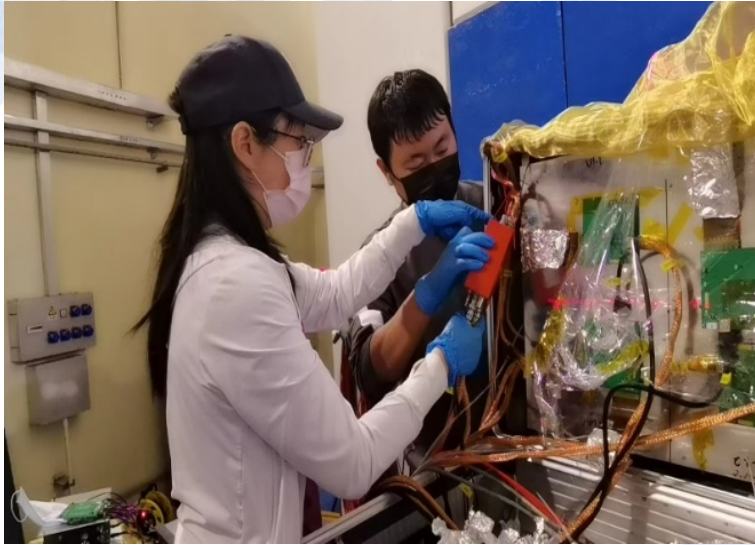
Map of Events



Neutron Imaging at CIAE



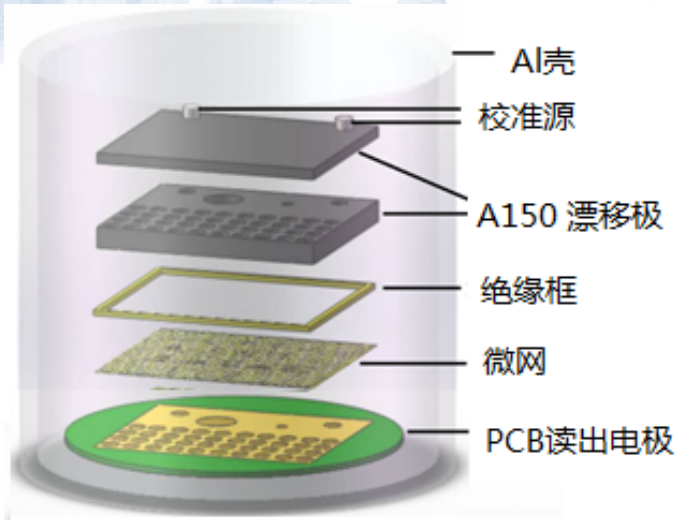
Neutron Imaging at CIAE 100MeV Cyclotron



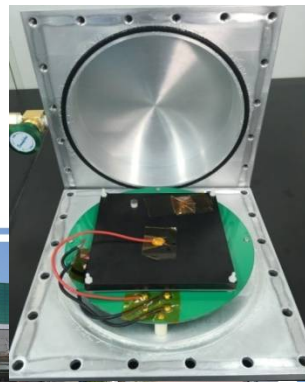
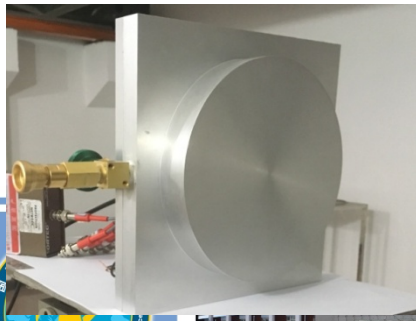
Using 70-100MeV to measure the cyclotron neutron beam at 28 points online. It is the cyclotron neutron beam spot monitored online for the first time



MicroMegas: TEPC at CIAE



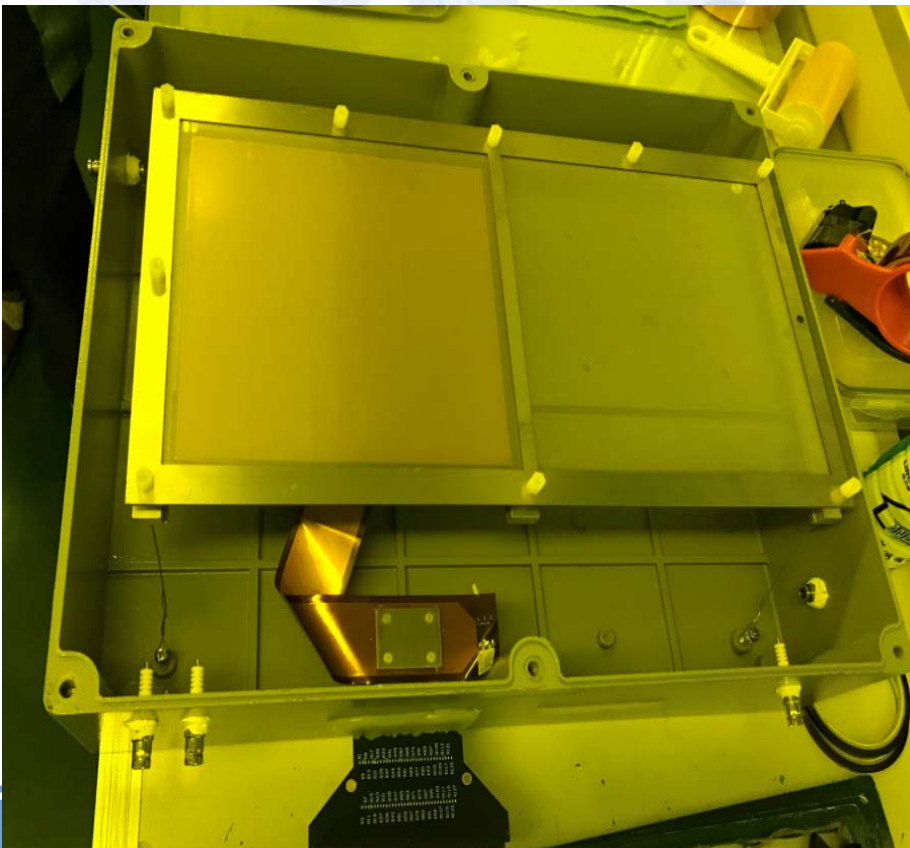
TEPC is widely used in microdosimetry.
**Compare with MWPC:
Easy Assembly,
More Sensitive**



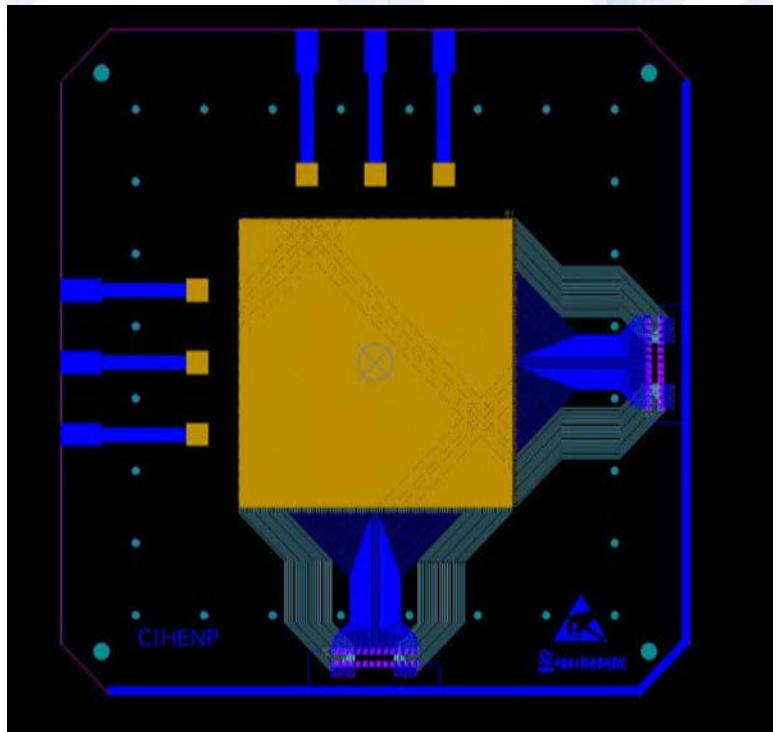
**Compare with GEM:
More stable**

**Tissue Equivalent
Proportional Counter**

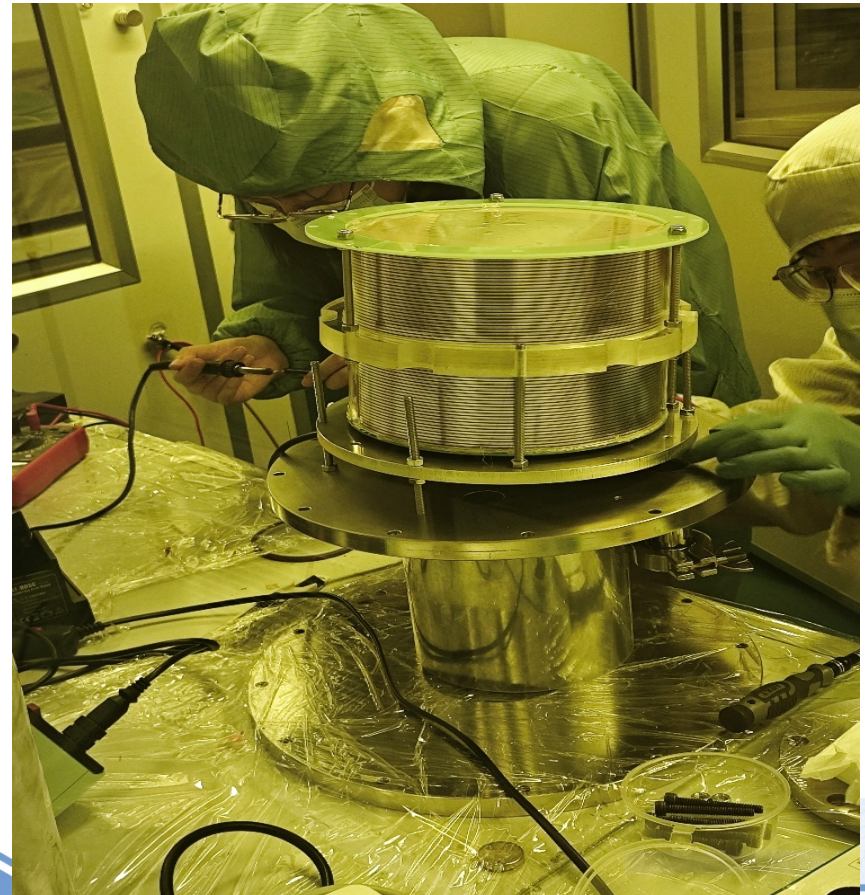
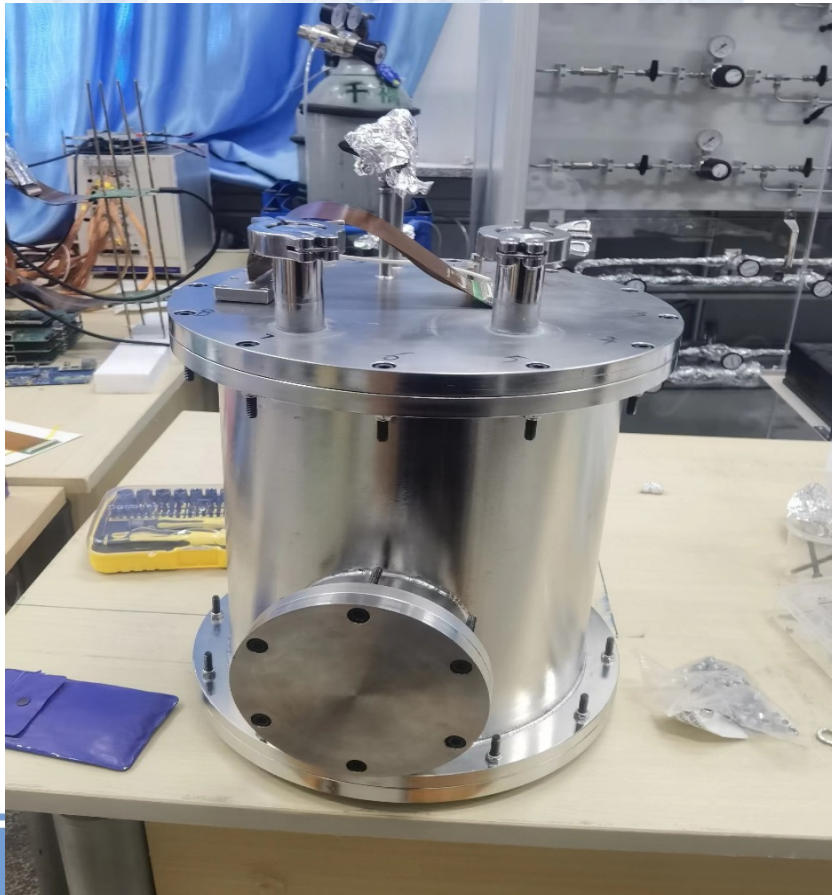
PandaX-III MM Test Platform at CIAE



MicroMegas for the R&D of CEPC TPC



MicroMegas for R&D of Multifunction TPC



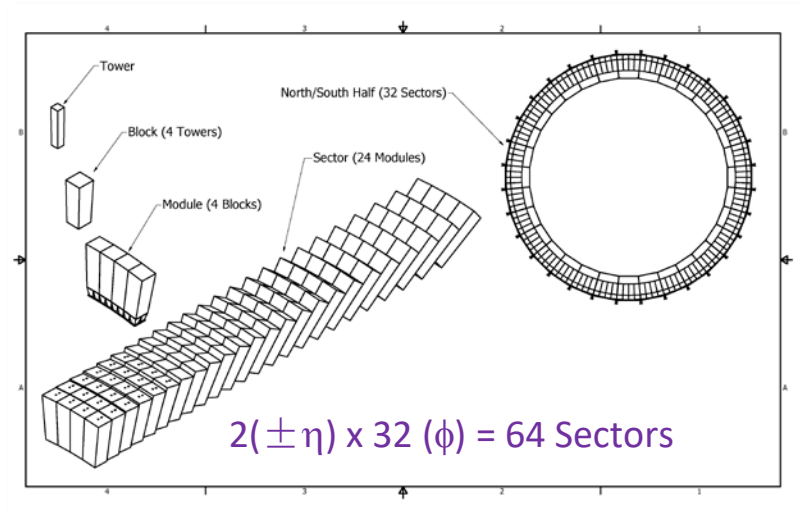
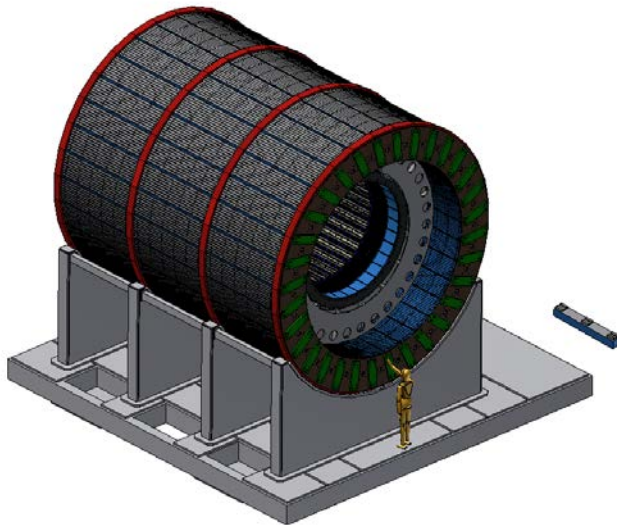
Development of EMCal Detector for sPHENIX



EMCal Design Performance

The EMCal (Electromagnetic Calorimeter) is an essential sub-detector for sPHENIX to measure the QGP near the critical temperature.

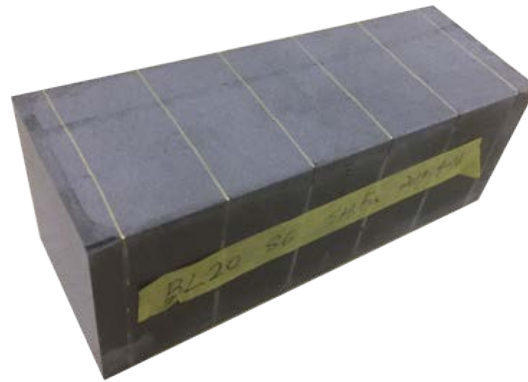
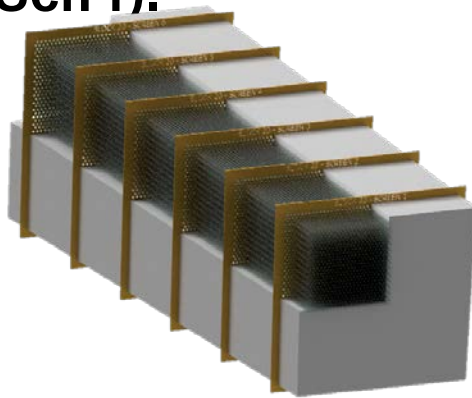
EMCal covering ± 1.1 in η and 2π in ϕ . $\Delta\phi \times \Delta\eta \sim 0.025 \times 0.025$



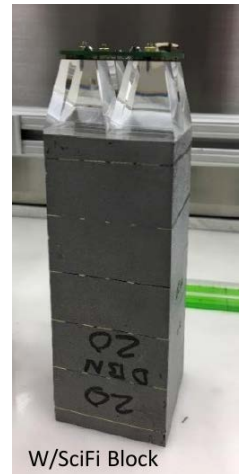
The EMCal performance is central to the direct photon and Upsilon measurements and it is also a key component, along with the HCal, of the jet reconstruction.

EMCal Block Design

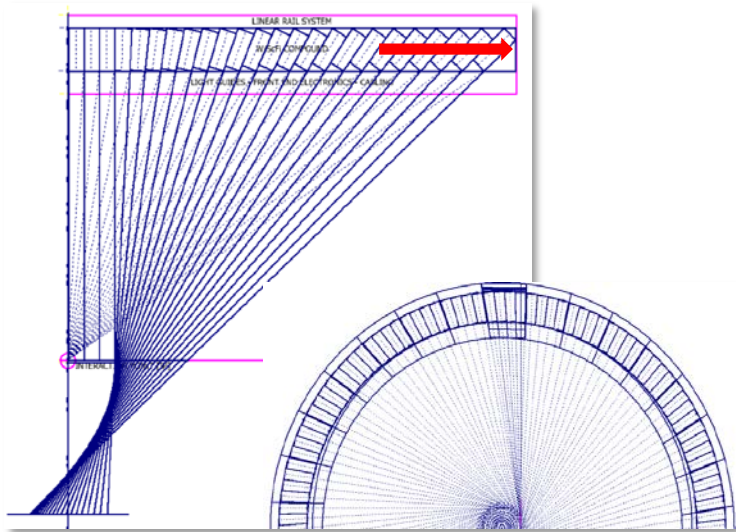
The EMCal block design consists of scintillating fibers embedded in the absorber material, which is a matrix of tungsten powder infused with epoxy (W/SciFi).



- High density (9-10 g/cm³), low radiation length (~7 mm), small Molière radius (~ 2 cm), compact structure and low cost.
- The readout system adopts light guide combined with SiPM.



The Contribution from China

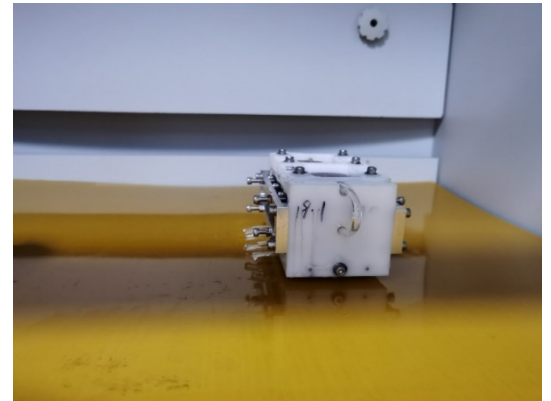
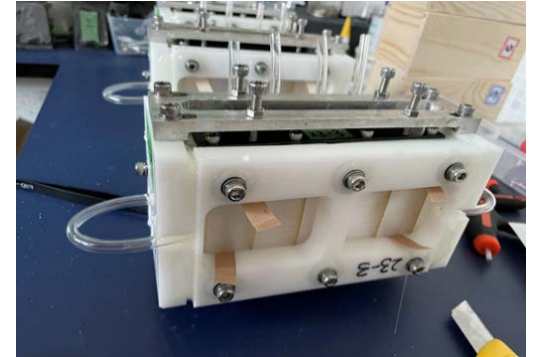


- Total 6144 blocks for EMCal
- 1248 blocks will be made in China.

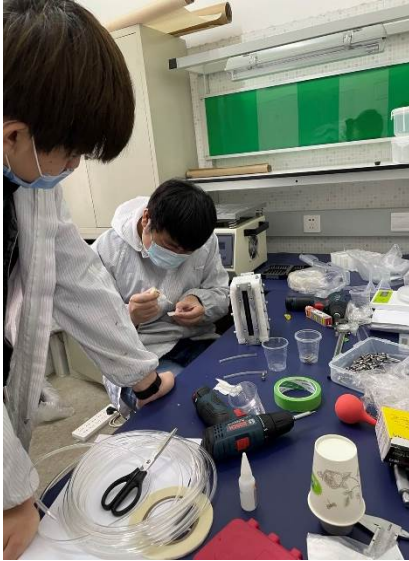
➤ Fudan, CIAE, and PKU are the main cooperative sites in EMCal construction and make an important contribution to the sPHENIX experiment.

sPHENIX EMCal R&D Center

- 2668 scintillating fibres in one block
- 6340 kg in total
- 97% finished product ratio



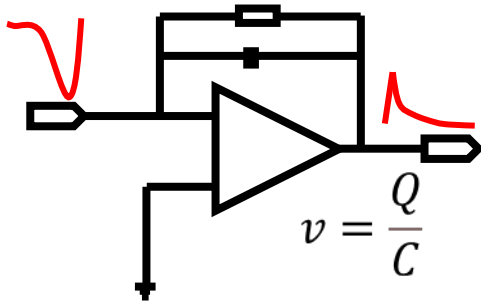
Block Mass Production



Block Mass Production

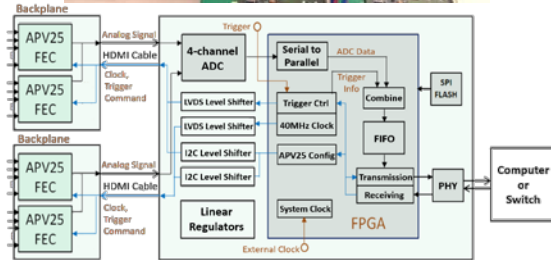


FPGA-Based Readout System for SiPM

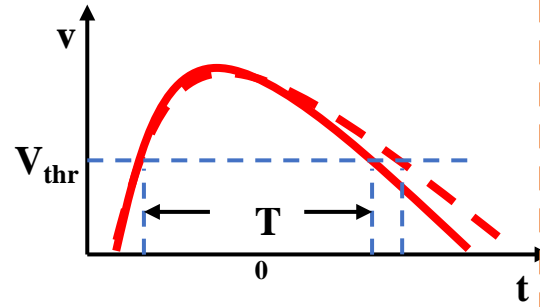


How to measure the voltage?

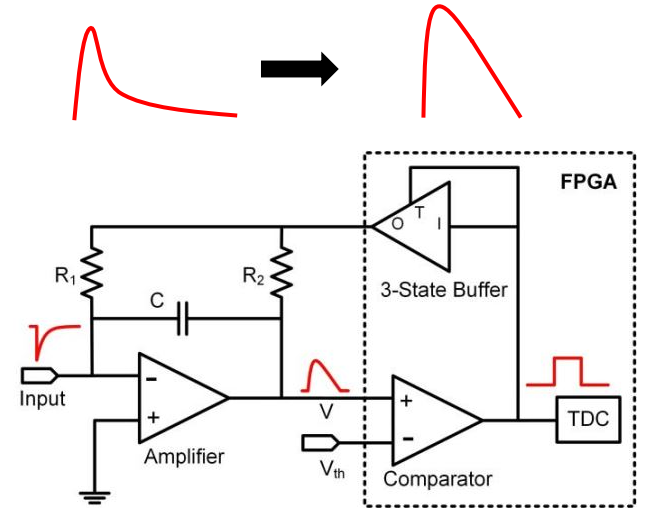
- ADC
- TOT
- FPGA-based method



APV readout system(adc-based)



TOT method



Flexible, low cost, fast speed

$$\int_0^{T_{start}} \frac{V}{R_1 + R_2} dt + \int_{T_{start}}^{T_{end}} \frac{U_0}{R_1} dt + CV_{th} = \int_0^{T_{end}} i(t) dt$$

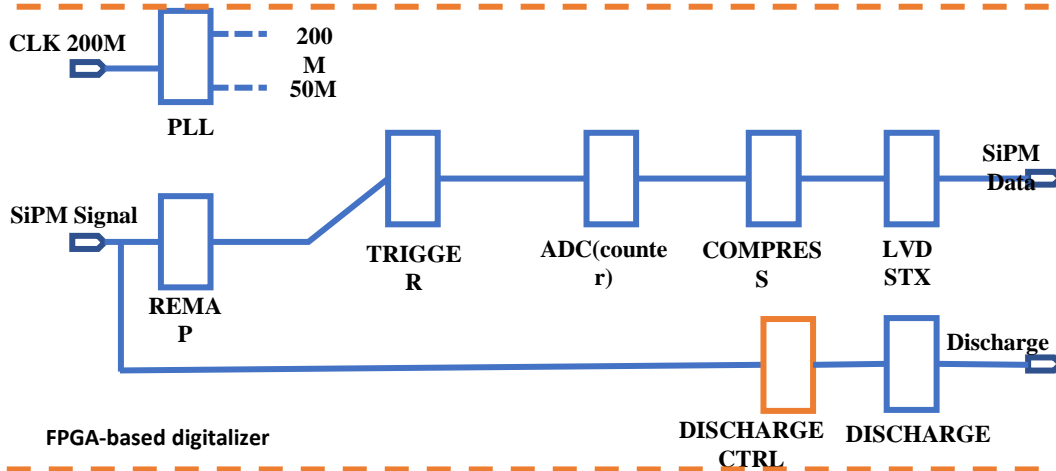
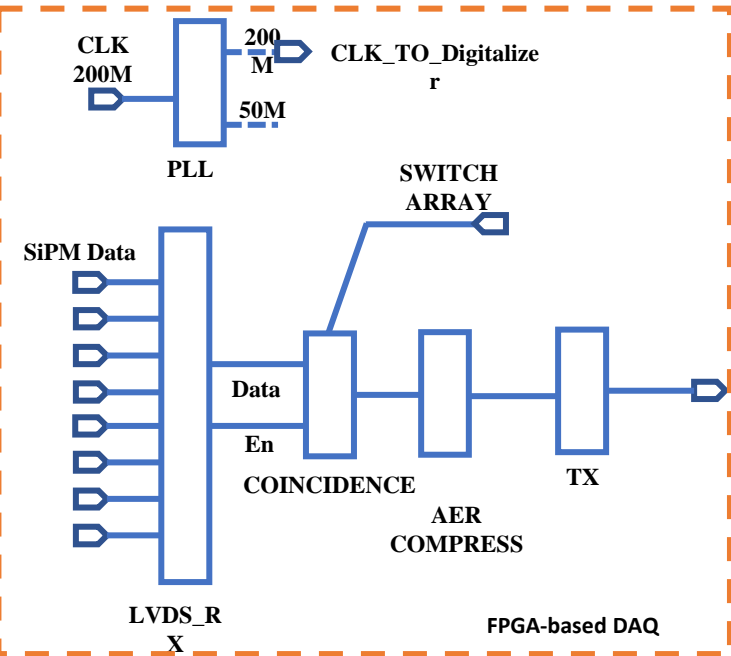
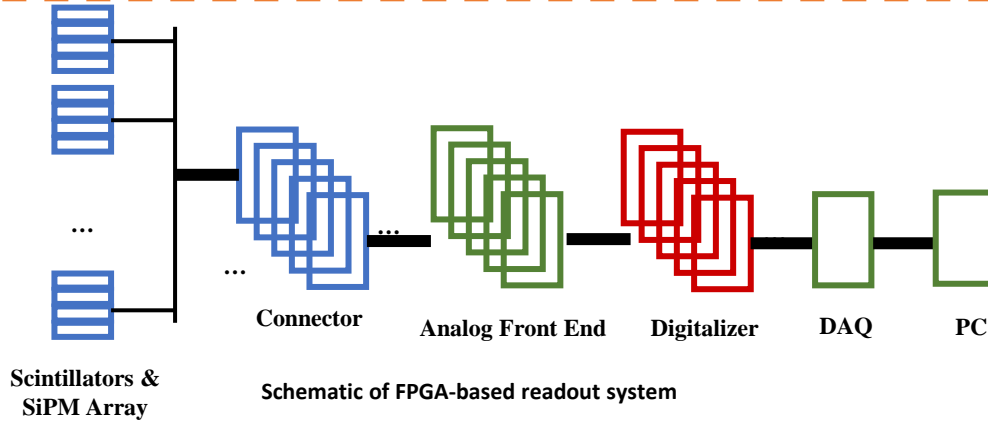
$$\frac{U_0}{R_1} (T_{end} - T_{start}) \approx \int_0^{T_{end}} i(t) dt \approx Q$$

TNS.2017.2648787

Linear discharge readout method (FPGA-based)

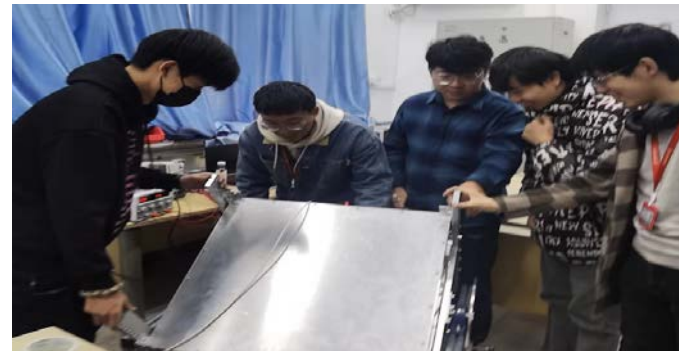
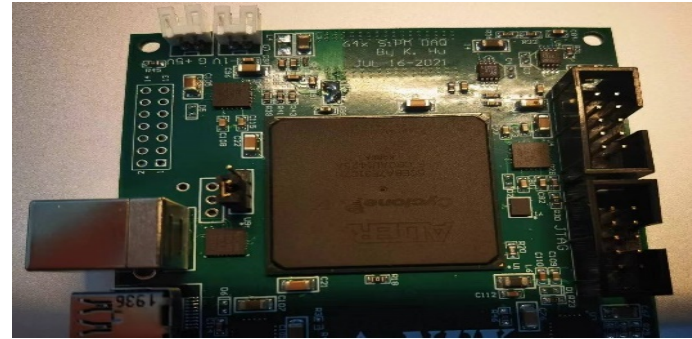
FPGA-based readout system

FPGA-based linear discharge electronics system for SiPMs.



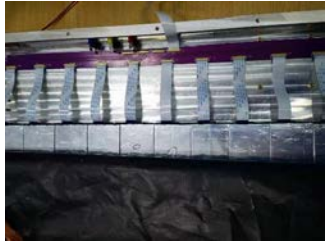
The main control FPGA of the digital board integrates functions such as discharge control and triggering, analog-to-digital conversion, and data compression. The FPGA of the data acquisition board integrates a coincidence module and a data compression module.

Scintillation Detector Array

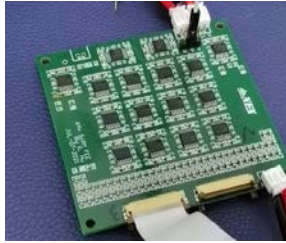


The test system with scintillators and SiPMs forming a detector array, connected to the analog front end via connectors, and the signal is digitized through a digitizer board and transmitted to a data acquisition board.

Cosmic ray test



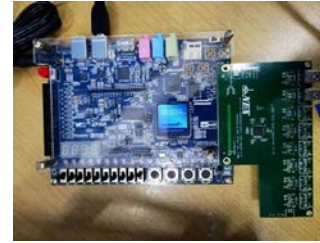
Detector



Analog Front End



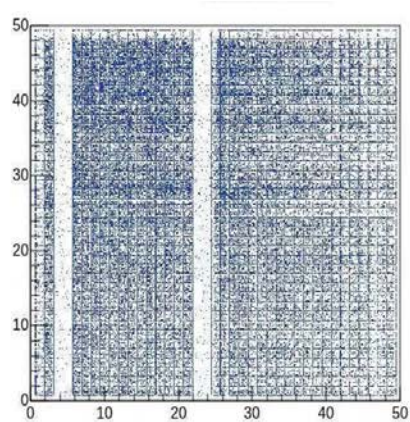
Digitalizer



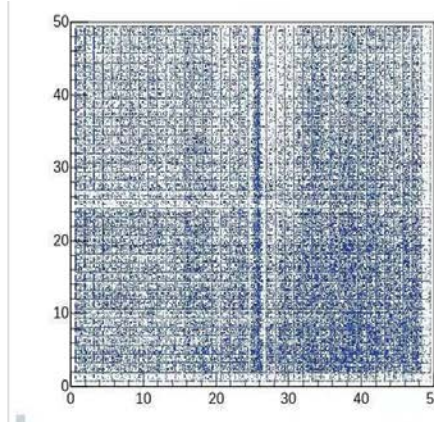
DAQ

we have carried out cosmic ray testing.

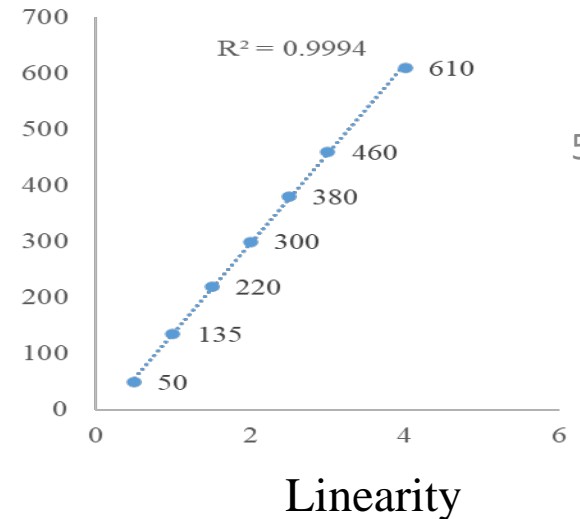
In addition, we estimate the linearity of the system, which is good.



xyfit	
Entries	191683
Mean x	24.46
Mean y	25.60
Std Dev x	13.74
Std Dev y	14.05

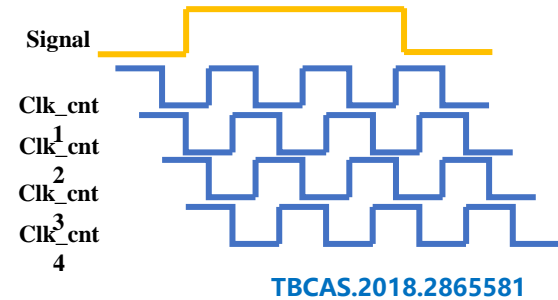
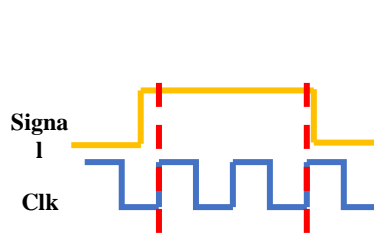
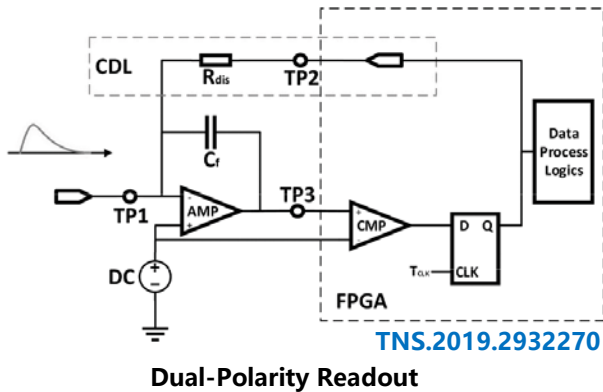


xyfit	
Entries	201408
Mean x	25.52
Mean y	24.45
Std Dev x	14.00
Std Dev y	14.01



cosmic ray event

Improvement of Readout System



Use Multiphase Counter Increase accuracy
trade-off between resource and precision

<p>Front board</p> <ol style="list-style-type: none"> 1. FEE front-end electronics board (suitable for direct connection detector) 2. Receiver board (acquire multiple digital signals) 3. Clock board, used as clock distribution, data acquisition 	<p>FPGA board</p> <ol style="list-style-type: none"> 1. Digitalizer 2. Data Aggregation 3. Data Processing 	<p>Interface</p> <ol style="list-style-type: none"> 1. Uart 2. USB3.0 3. Optical communication 4. Data & CLK Port 5. Ethernet port
<p>PWR JTAG...</p>		

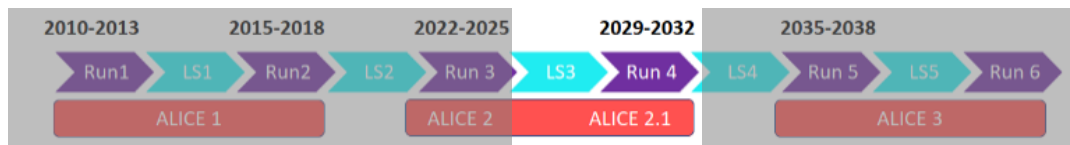
● **FPGA upgrade for IOs and power consumption**

● **Deploy some algorithms on the FPGA, such as noise filters, data compression**

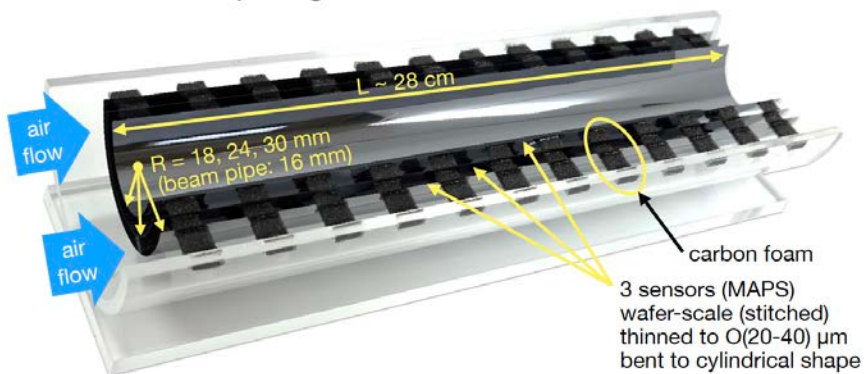
ALICE Upgrade



The ALICE 2.1

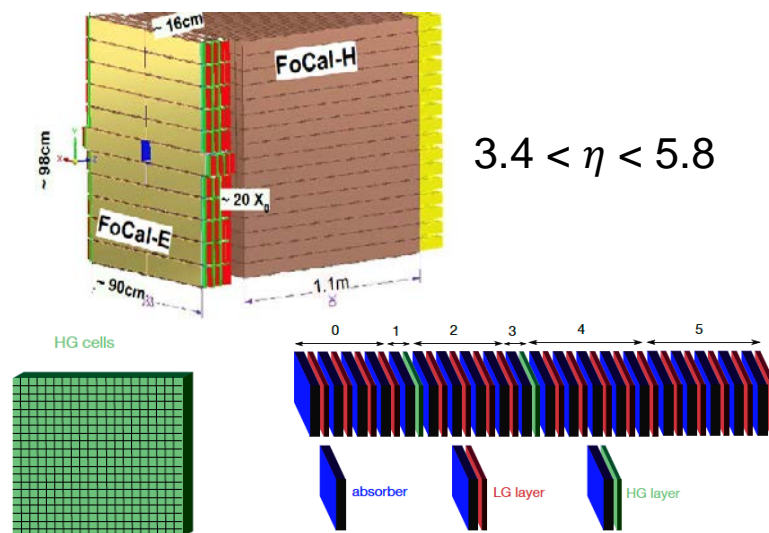


Stitching MAPS-based ITS3



- Replacement of 3 innermost layers of ITS2
- Curved **wafer-scale ultra-thin** silicon sensors: cylindrical layers (1 sensor per half layer)
- Low power → air cooling → low material budget
- Improved tracking precision and efficiency at low p_T

Silicon-based FoCal



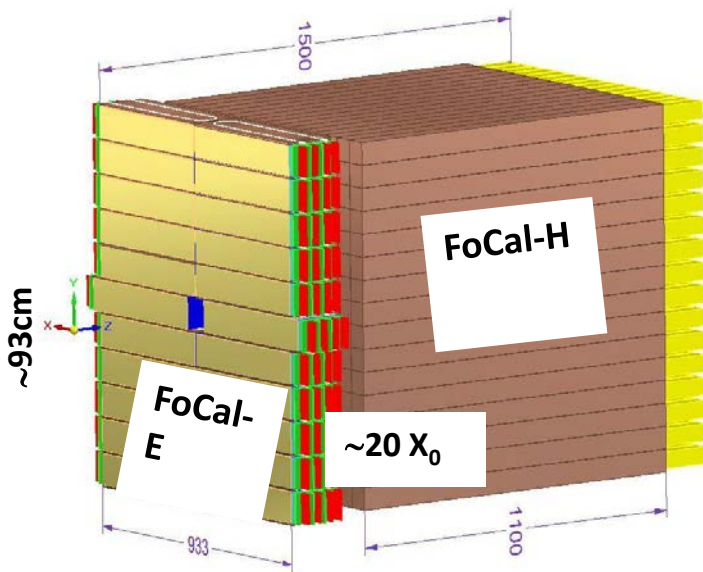
- ✓ Pad (1x1 cm²): shower profile and total energy
- ✓ Pixel (30x30 μm²): position resolution to resolve overlapping showers

ALICE 2.1 – FoCal Detector

FoCal-H

Spaghetti-like hadronic calorimeter

- Copper tubes with length of 110 cm $\sim 7\lambda_I$ (length constrained by space)
- Inside the copper tubes are scintillating optical fibers
- readout using SiPMs



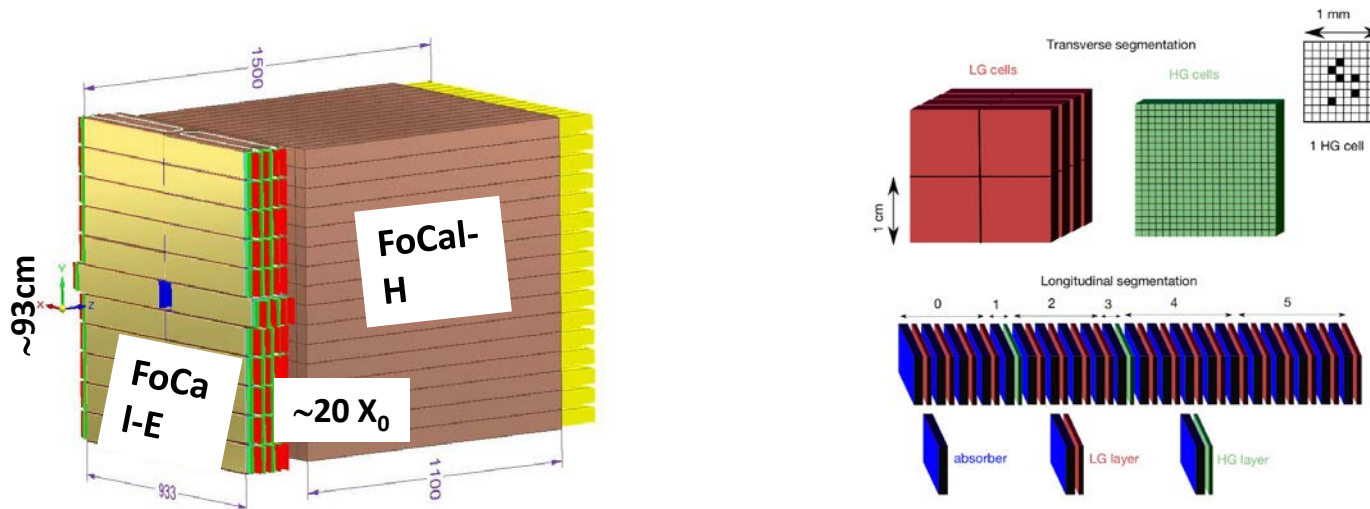
FoCal-H prototype, 9 x (6.5 x 6.5 x 110 cm³)

ALICE 2.1 – FoCal Detector

FoCal-E

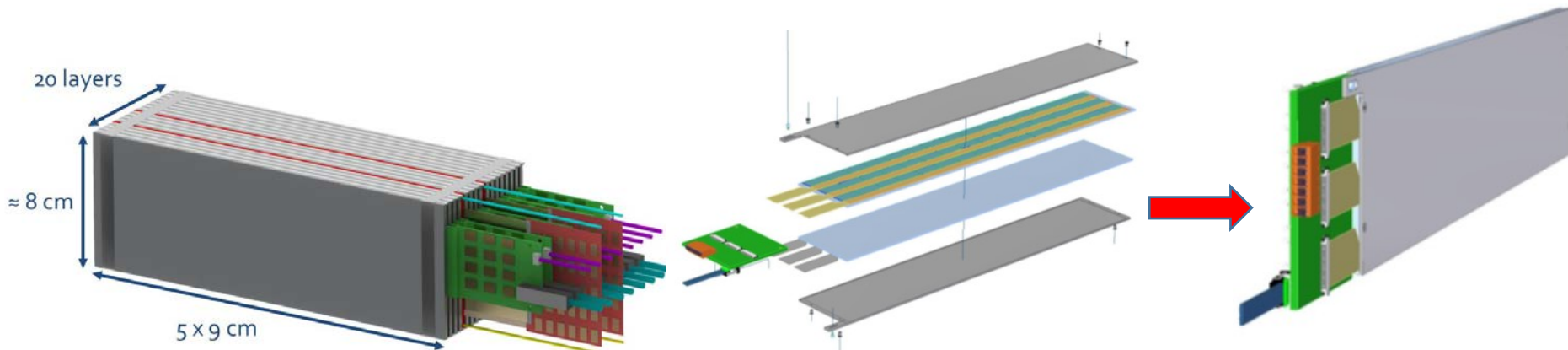
Silicon and tungsten constitute an electro-magnetic calorimeter with an equivalent granularity of approximately 1 mm^2

- 20 layers: Tungsten ($3.5 \text{ mm} \approx 1X_0$) + Silicon sensor
- Two types: Silicon strip (LG) and Silicon pixel (HG).
- Silicon strip provides cluster shape information
- Pixel layer provides high position resolution to resolve clusters with partial overlap

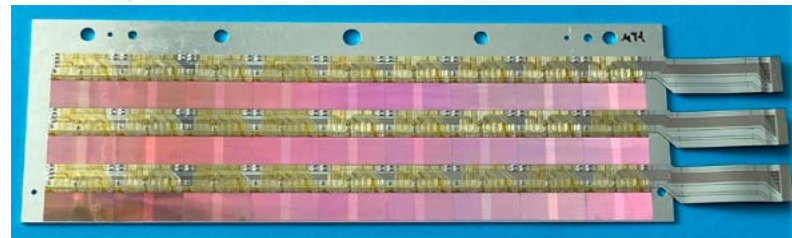


ALICE 2.1 – FoCal-E module

FoCal-E



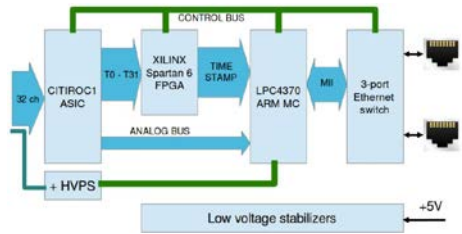
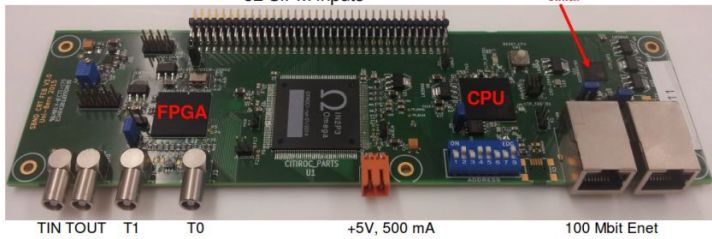
- **Sensitive region:** 45 cm x 8 cm
- **power distribution, data control, and transmission**
- **Capable of vertical stacking to form a complete detector.**
- **A total of 22 modules**



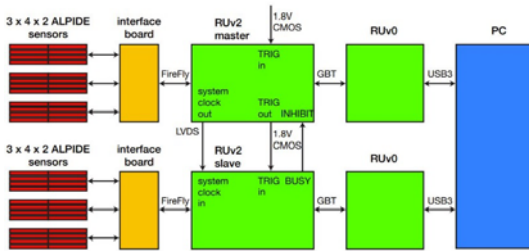
- **A long strip composed of 15 ALPIDE chips**
- **2 x 3 long strips form the silicon pixel layer module**
- **Each module contains 90 ALPIDE chips**
- **44 silicon pixel modules, totally 3960 ALPIDE chips**

ALICE 2.1-Focal Readout Electronics

M. Auger et al 2016 JINST 11 P10005
32 SiPM inputs

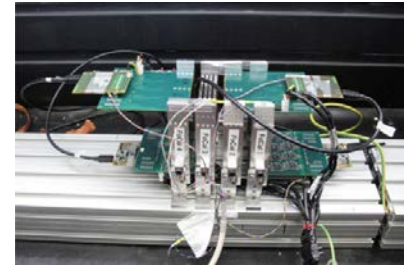
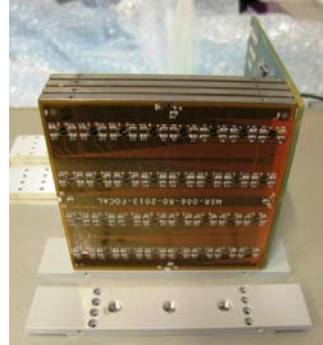


FoCal-H 2021 prototype readout electronics



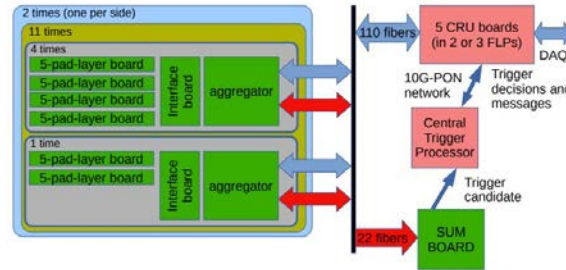
arXiv:2209.02511

FoCal-E pixel layer prototype EPICAL-2 readout electronics

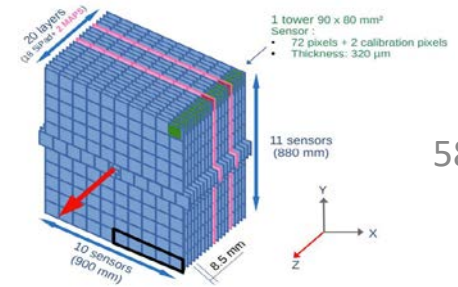


arXiv:1912.11115

For the readout electronics of Focal-H, with a focus on the readout of the SiPM, a number of prototype electronics have been developed that use an ASIC as an analog front-end and an FPGA as a digital back-end. In the case of Focal-E, the electronics scheme chosen is also different due to the different granularity of the pad layer and the pixel layer.

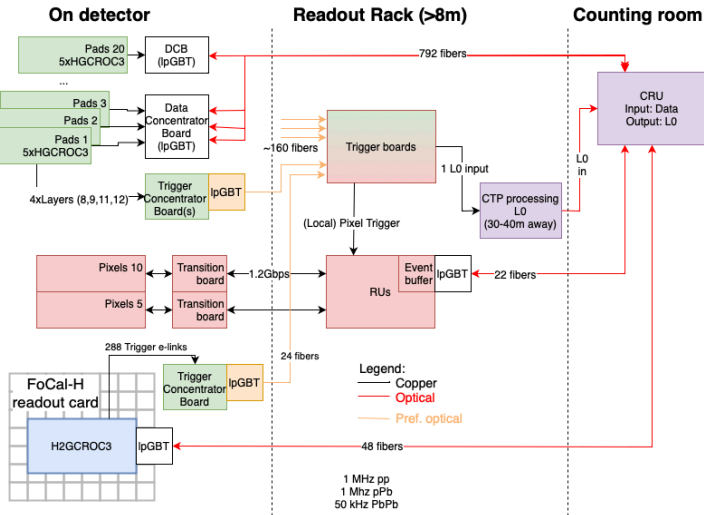


FoCal-E pad layer prototype readout electronics



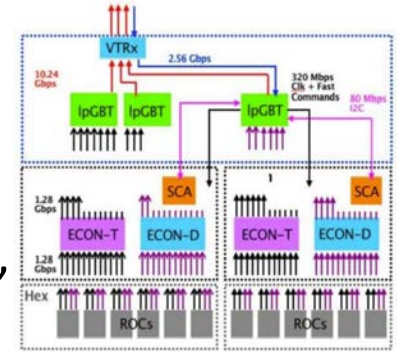
arXiv:2302.13912

ALICE 2.1-Focal Readout System

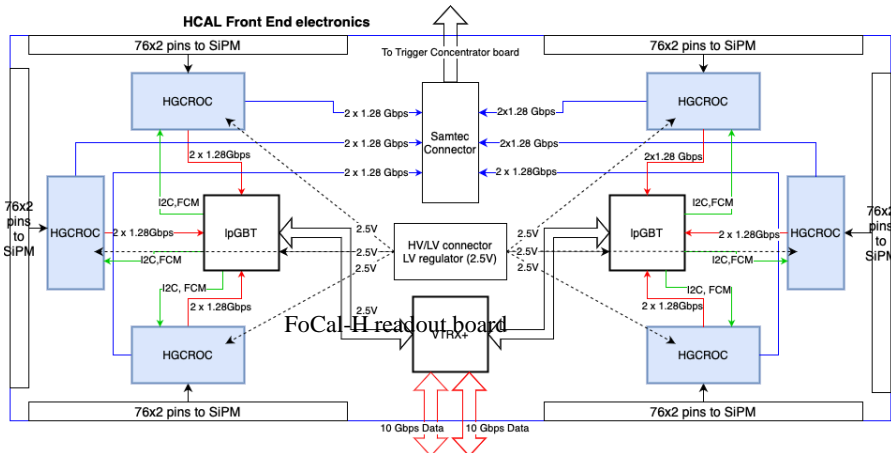


FoCal readout system

Focal Electronics' research borrowed part of the CMS design, and it is planned to use HGCROC as the front-end chip, ECON chip for data compression, IpGBT chip for data transmission, and FPGA for control.



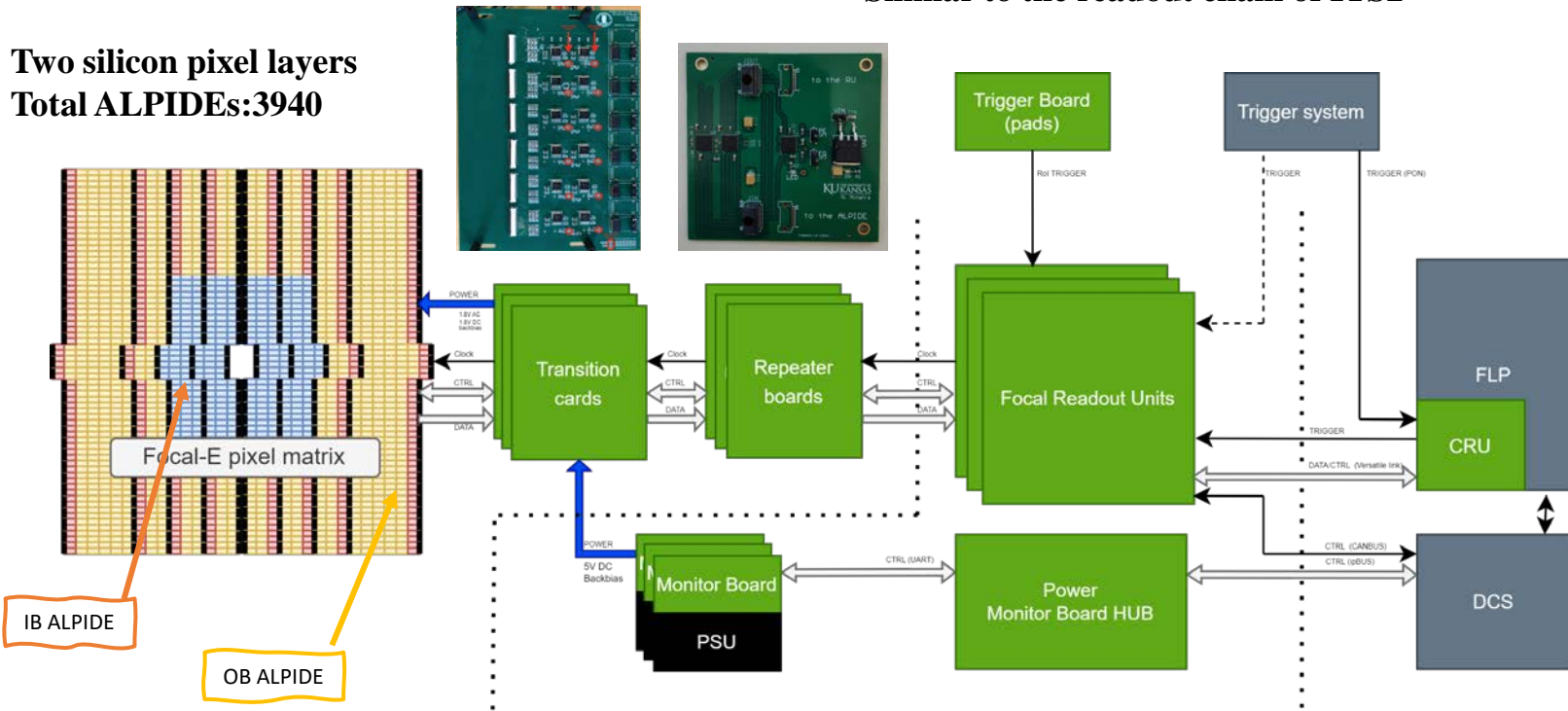
CMS CR -2021/228



- Protect FPGAs with Long Readout Rack
- Use ECON-D and IpGBT readout pixel data
- ALPIDE pixels use continuous trigger mode, or through signals provided by the Pad layer
- 6 HGCROC, 2 LpGBT, 1 VTRx+
- 6x72 = 432 channels
- Use ECON-D / ECON-T ASIC compress data

ALICE 2.1 – Readout chain for the silicon pixel layer

Two silicon pixel layers
Total ALPIDEs:3940



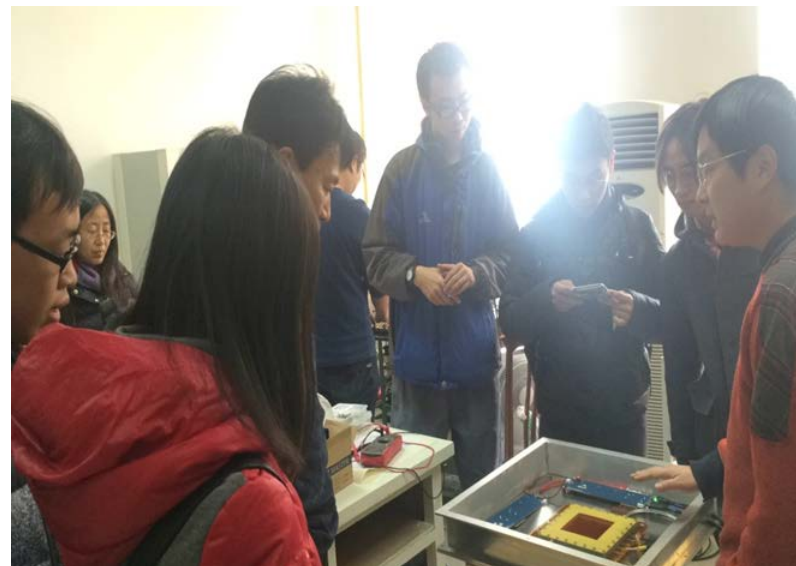
The readout link of the whole silicon pixel layer is extremely similar to the readout link of ITS2. There are some readout units, which we have to make some improvements.

CIAE Intermediate and High Energy Physics Team Members

- 2 Professors
- 1 Associate Professor
- 1 Assistant Professor
- 3 Technicians
- ~12 Students



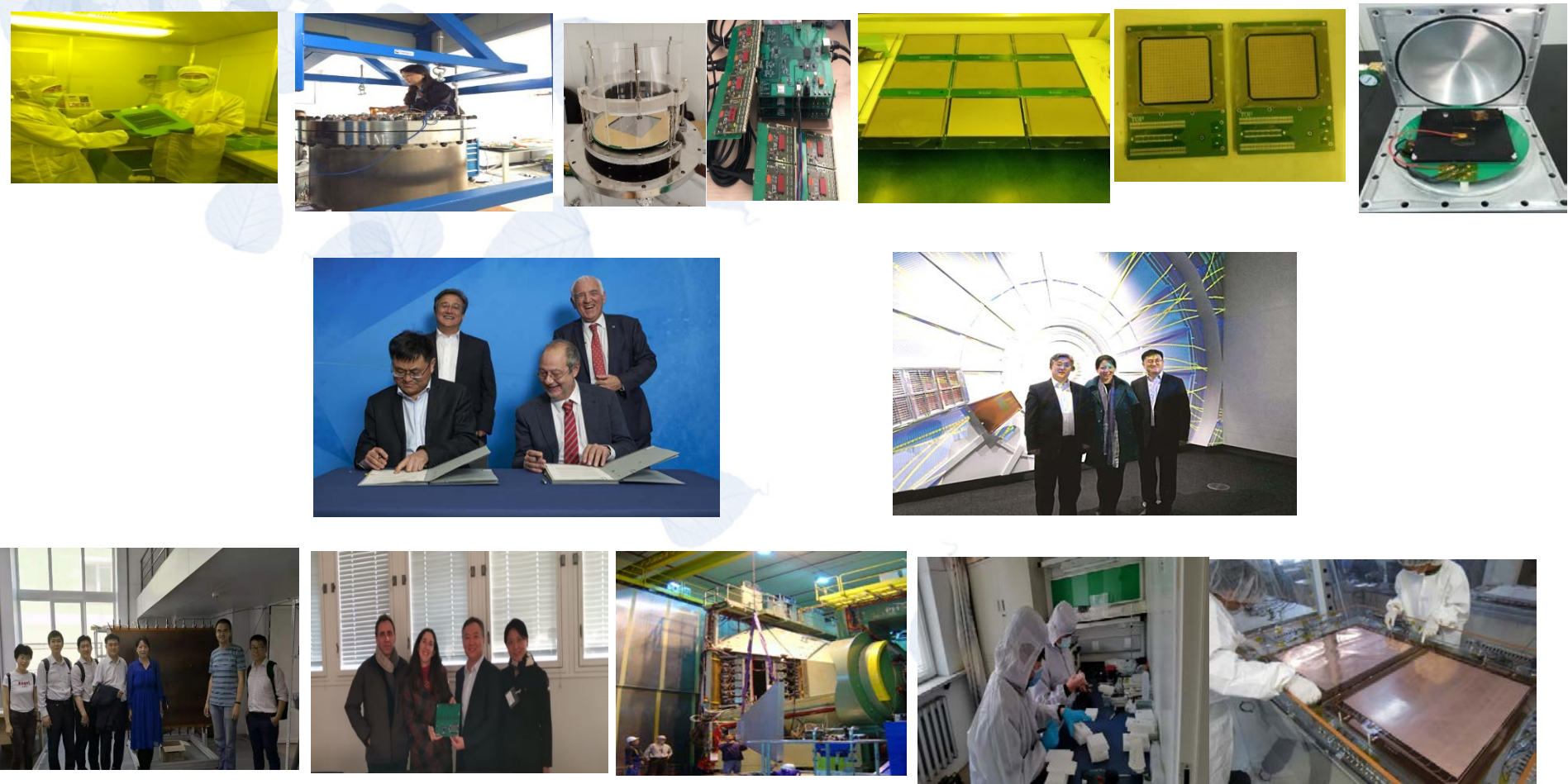
Visitors



Summary and Prospect

- 1. Complete R&D and mass production of photoetching MicroMegas.**
- 2. Complete R&D and mass production of scintillating fibre detectors.**
- 3. Electronics for MPGD and Electronics for SiPM developed by our team works well.**
- 4. A new scintillating fibre detector lab will be builded.**

Detector Applications and Collaborations



Thanks for your attention!

